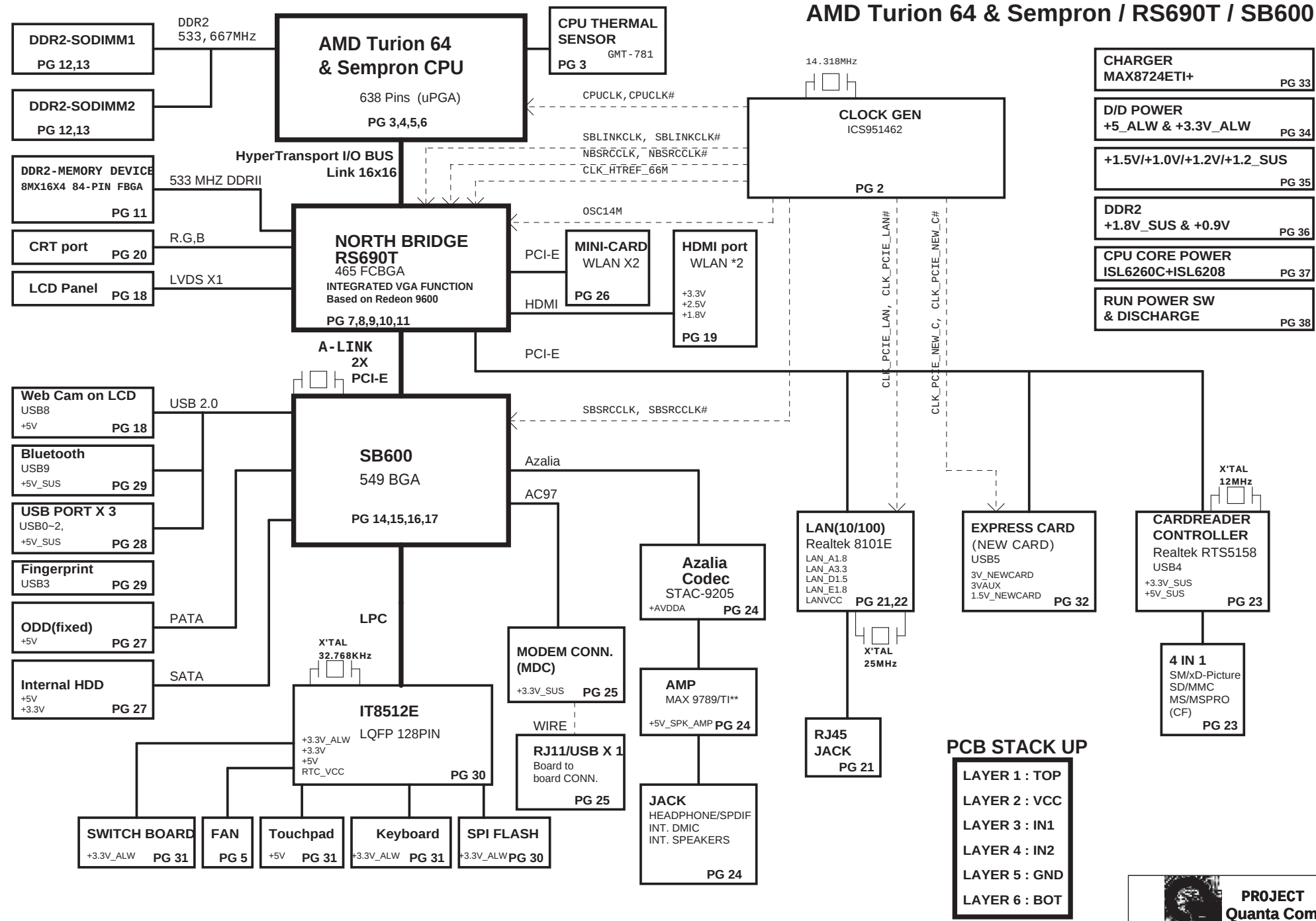
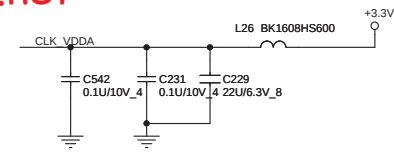
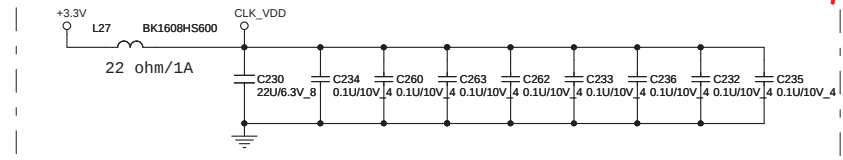


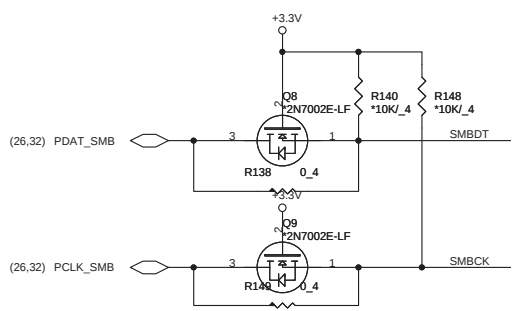
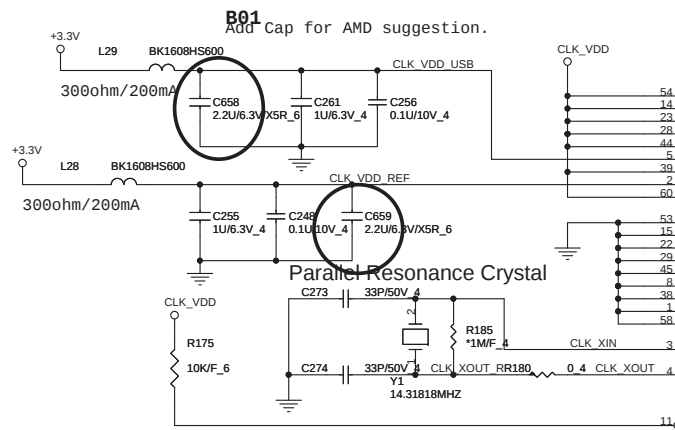
SA1A BLOCK DIAGRAM

AMD Turion 64 & Sempron / RS690T / SB600





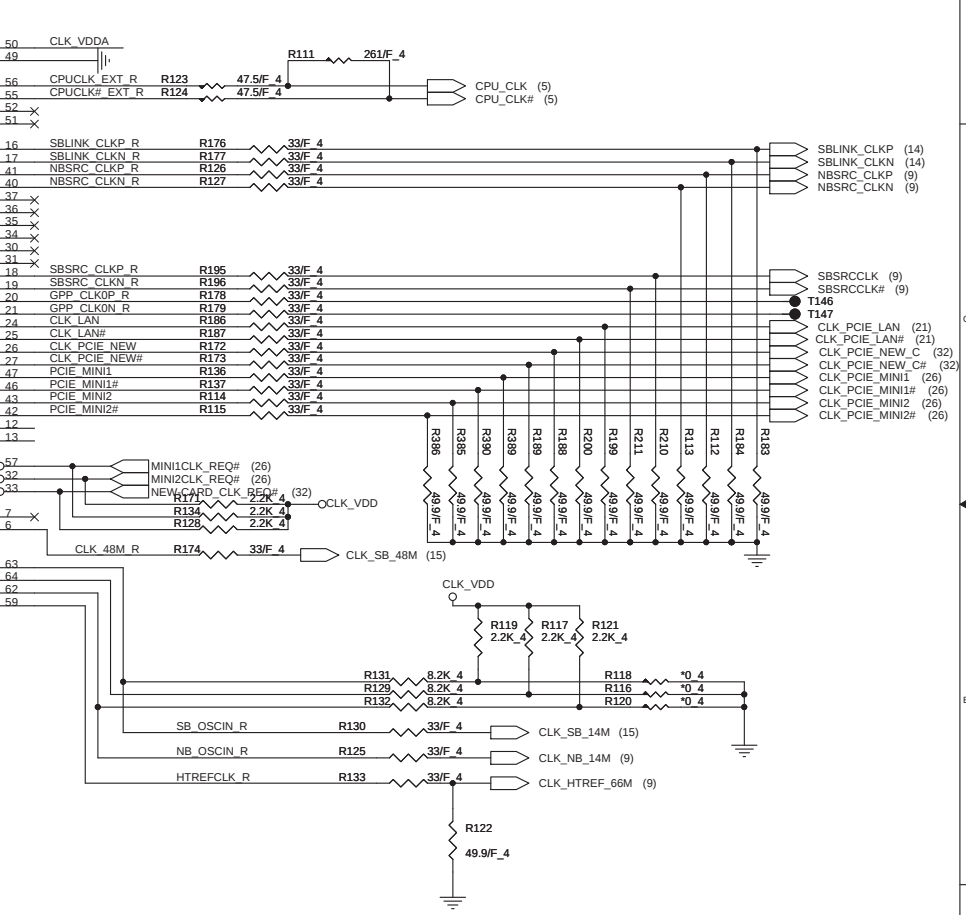
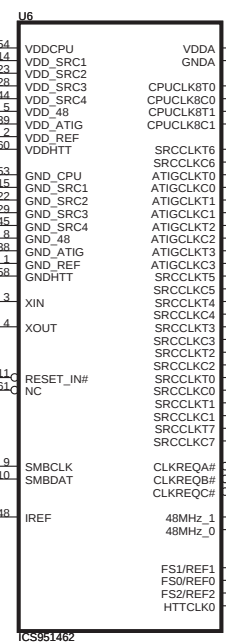
- 1- PLACE ALL SERIAL TERMINATION RESISTORS CLOSE TO U800
- 2- PUT DECOUPLING CAPS CLOSE TO Clock Gen.POWER PIN



$$I_{oh} = 5 * I_{ref} \quad (2.32mA)$$

$$V_{oh} = 0.71V @ 60 ohm$$

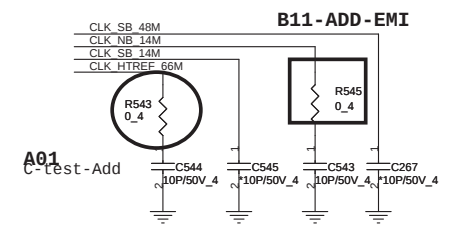
CLKREQA# CONTROL SRC5,6,7
CLKREQB# CONTROL SRC2,3,4
CLKREQC# CONTROL SRC0,1

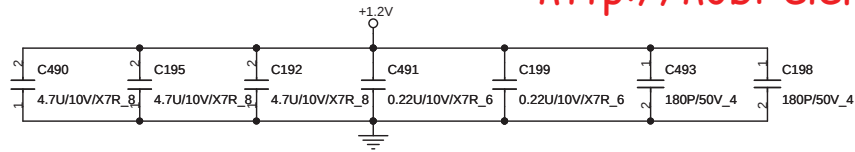


EXT CLK FREQUENCY SELECT TABLE(MHZ)

FS2	FS1	FS0	CPU	SRCCLK [2:1]	HTT	PCI	USB	COMMENT
0	0	0	Hi-Z	100.00	Hi-Z	Hi-Z	48.00	Reserved
0	0	1	X	100.00	X/3	X/6	48.00	Reserved
0	1	0	180.00	100.00	60.00	30.00	48.00	Reserved
0	1	1	220.00	100.00	36.56	73.12	48.00	Reserved
1	0	0	100.00	100.00	66.66	33.33	48.00	Reserved
1	0	1	133.33	100.00	66.66	33.33	48.00	Reserved
1	1	1	200.00	100.00	66.66	33.33	48.00	Normal ATHLON64 operation

Check AMD clock



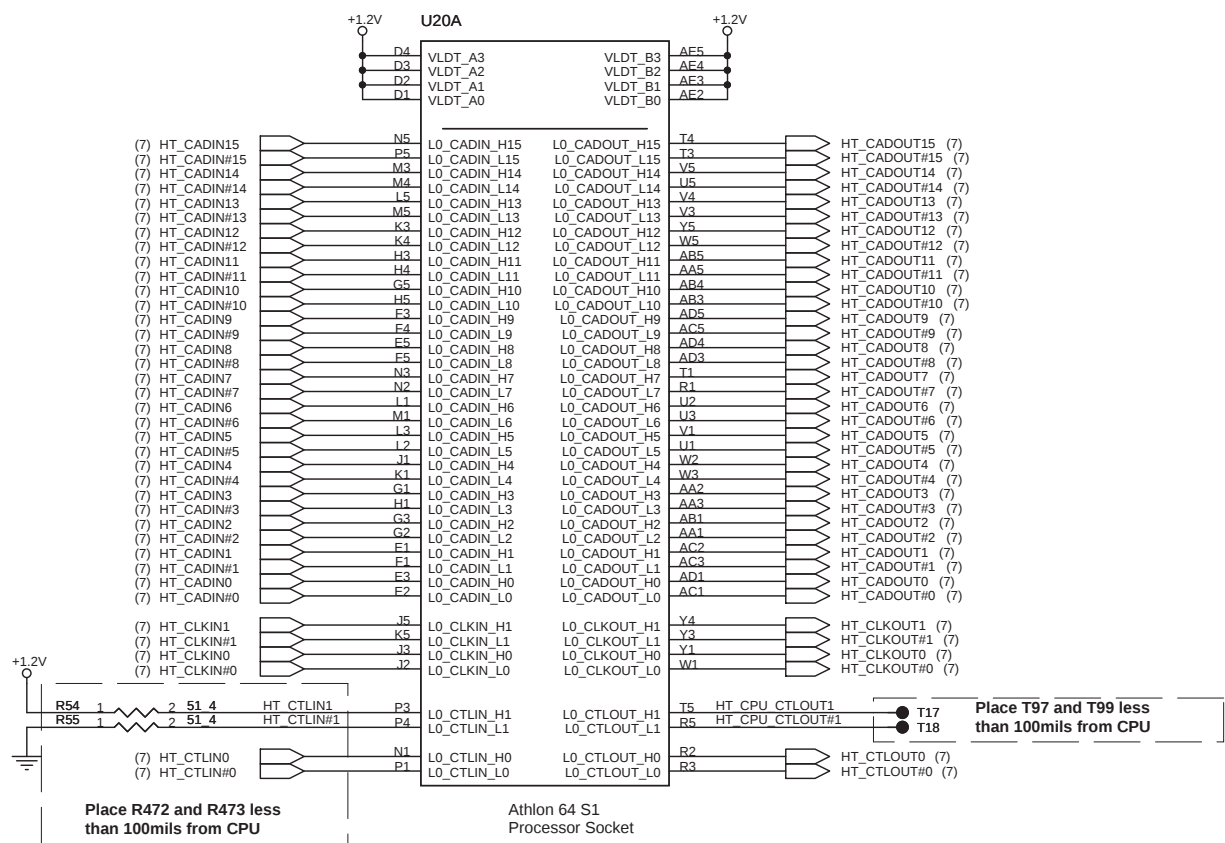


LAYOUT: Place bypass cap on topside of board

NEAR HT POWER PINS THAT ARE NOT CONNECTED DIRECTLY TO DOWNSTREAM HT DEVICE, BUT CONNECTED INTERNALLY TO OTHER HT POWER PINS
PLACE CLOSE TO VLDT0 POWER PINS

PROCESSOR HYPERTRANSPORT INTERFACE

VLDT_Ax AND VLDT_Bx ARE CONNECTED TO THE LDT_RUN POWER SUPPLY THROUGH THE PACKAGE OR ON THE DIE. IT IS ONLY CONNECTED ON THE BOARD TO DECOUPLING NEAR THE CPU PACKAGE



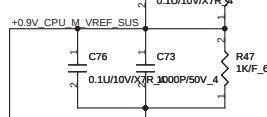


PROJECT : SA1A
Quanta Computer Inc.

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ATHLON64 HT I/F		
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VDD_VTT_SUS_CPU is CONNECTED TO THE VDD_VTT_SUS POWER SUPPLY THROUGH THE PACKAGE OR ON THE DIE. IT IS ONLY CONNECTED ON THE BOARD TO DECOUPLING NEAR THE CPU PACKAGE

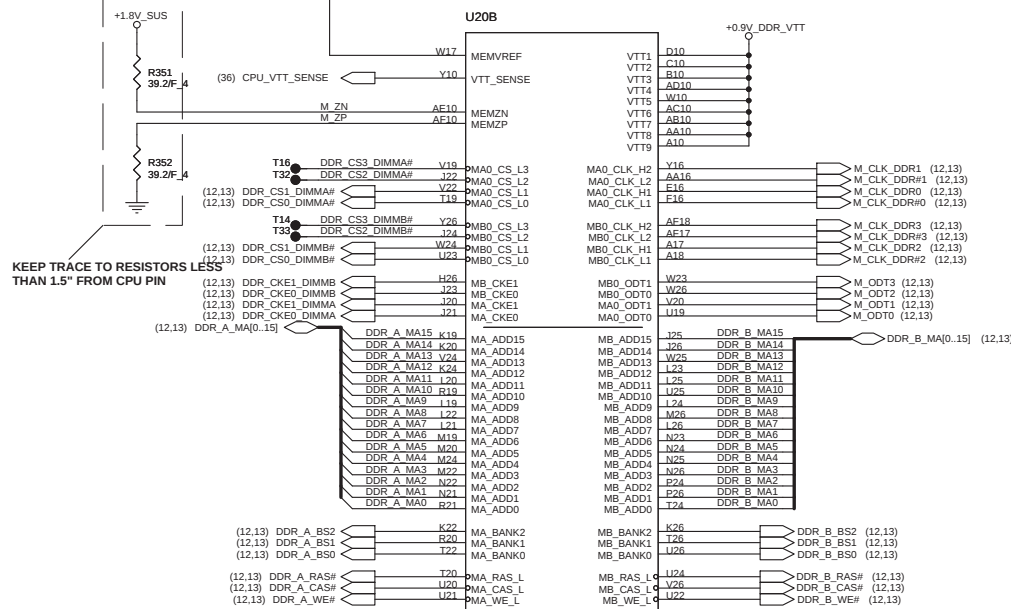
CPU_VTT_SUS_SENSE should be routed as 10mils and 10mils spacing from any adjacent signals in X, Y, Z directions.



Place Capacitors for +0.9V_CPU_M_VREF_SUS < 1" from the RS690. +0.9V_CPU_M_VREF_SUS trace length < 6", trace width > 15mils and 20mils spacing from any adjacent signals in X, Y, Z directions.

for +0.9V_DDR_VTT feedback

KEEP TRACE TO RESISTORS LESS THAN 1.5" FROM CPU PIN



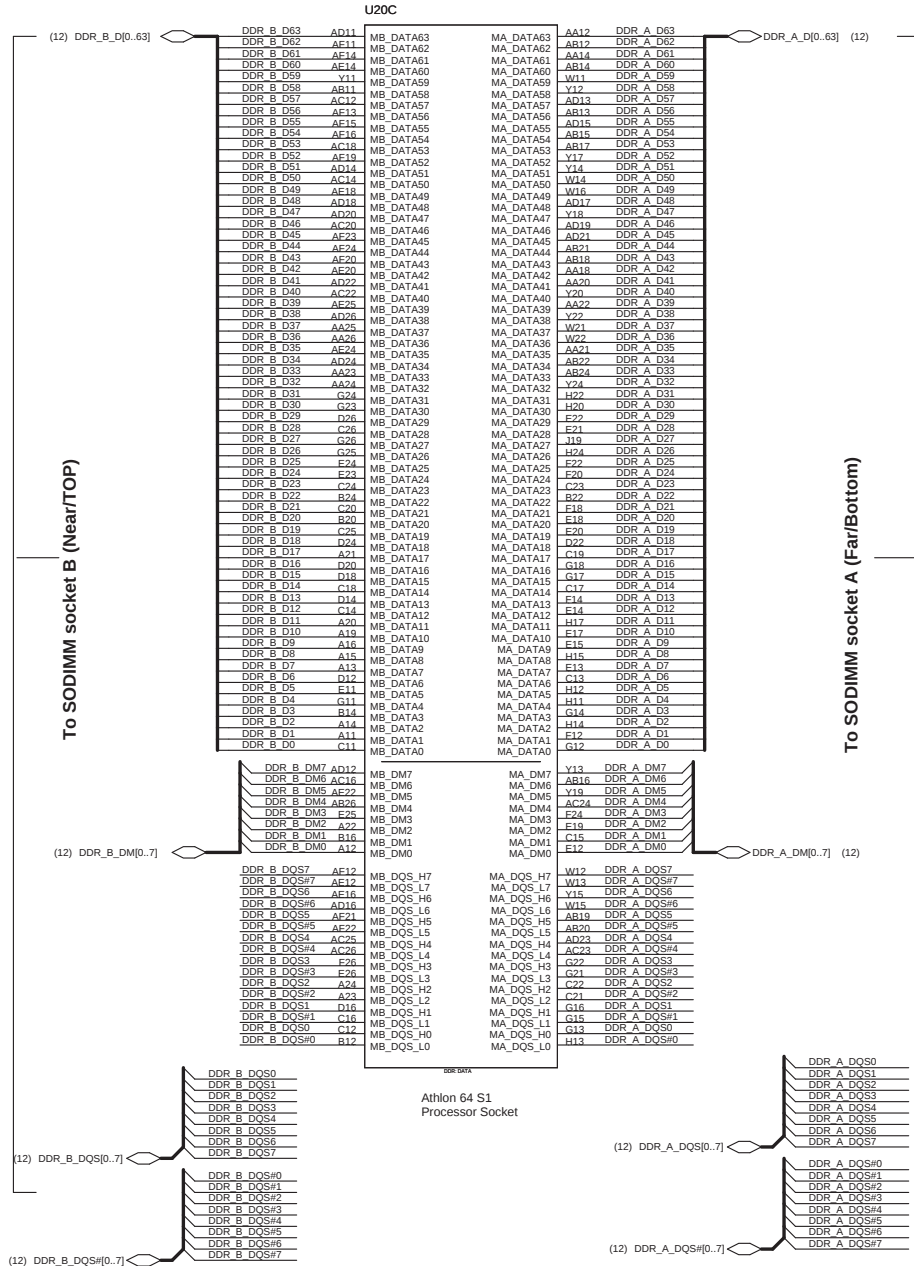
DDR B CMD/CTL/CLK

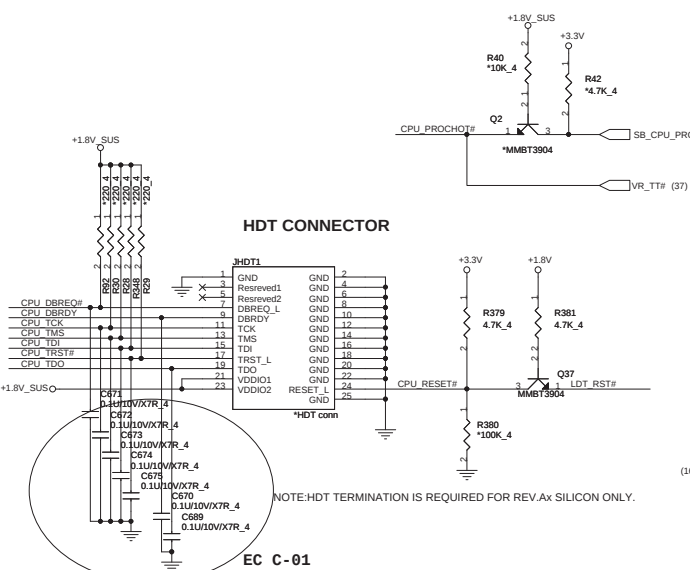
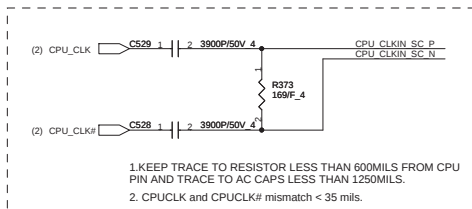
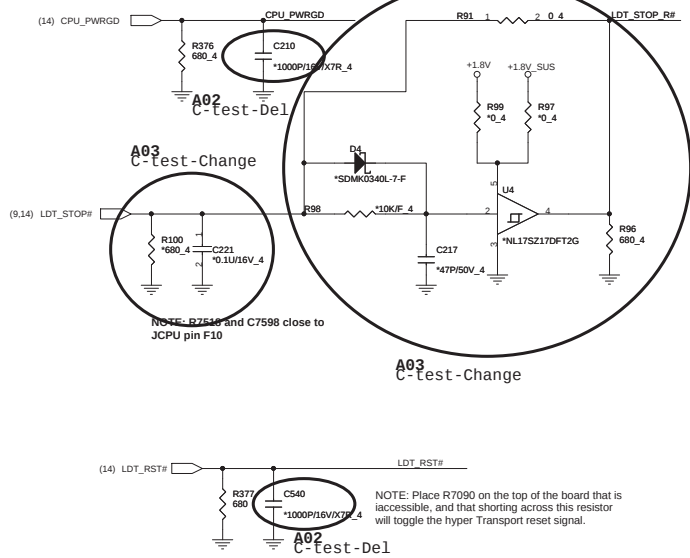
Athlon 64 S1

Processor Socket

Notes for the SDRAM locations:
DIMMA = Far = Bottom
DIMMB = Near = Top

Processor DDR2 Memory Interface





L65 ferrite bead with an approximate impedance of 33, a maximum DC resistance of 0.025 ohm, and a current rating of at least 3000mA.

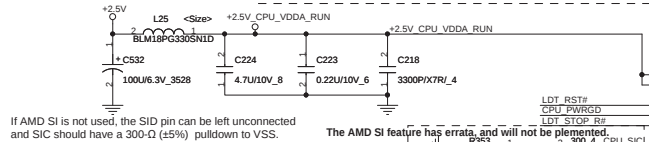
LAYOUT: ROUTE VDDA TRACE APPROX.

50 mils WIDE (USE 2x25 mil TRACES TO

EXIT BALL FIELD) AND 500 mils LONG.

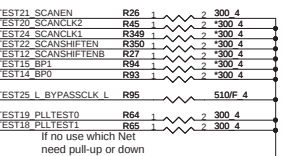
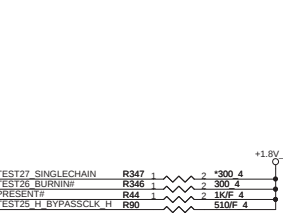
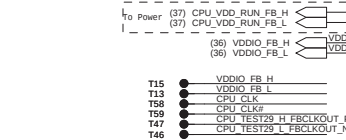
This trace should be kept at least 20 mils away from all other signals.

+2.5V_CPU_VDDA_RUN

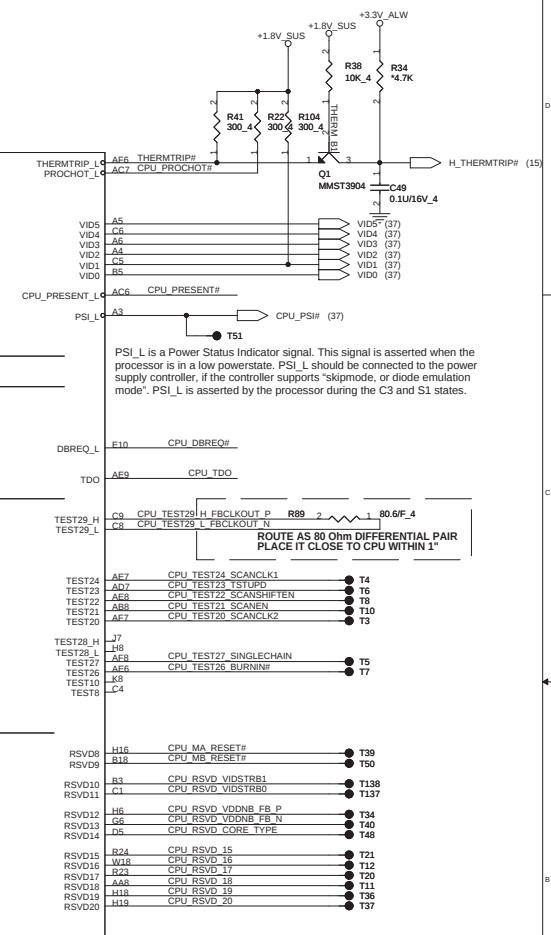
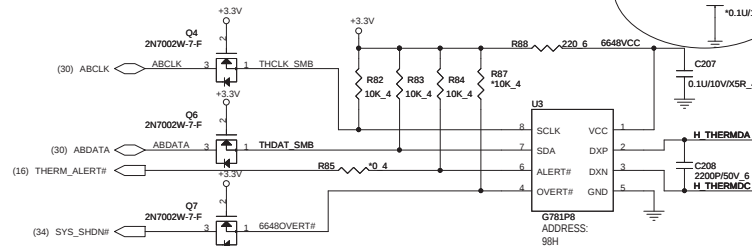


Place R78 and R77 < 1.5".

Route CPU_HTRF0 with 5mils trace width and 10mils spacing from other signals in X, Y, Z directions



CPU Thermal monitor



AMD NPT S1 SOCKET

Processor Socket

30 mil

30 mil

30 mil

30 mil

30 mil

30 mil

30 mil

30 mil

30 mil

30 mil

30 mil

30 mil

30 mil

30 mil

30 mil

30 mil

30 mil

30 mil

30 mil

30 mil

30 mil

30 mil

30 mil

30 mil

30 mil

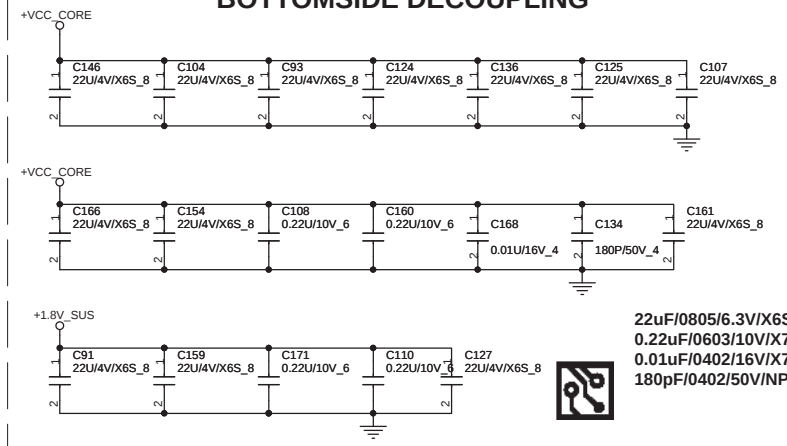
30 mil

30 mil

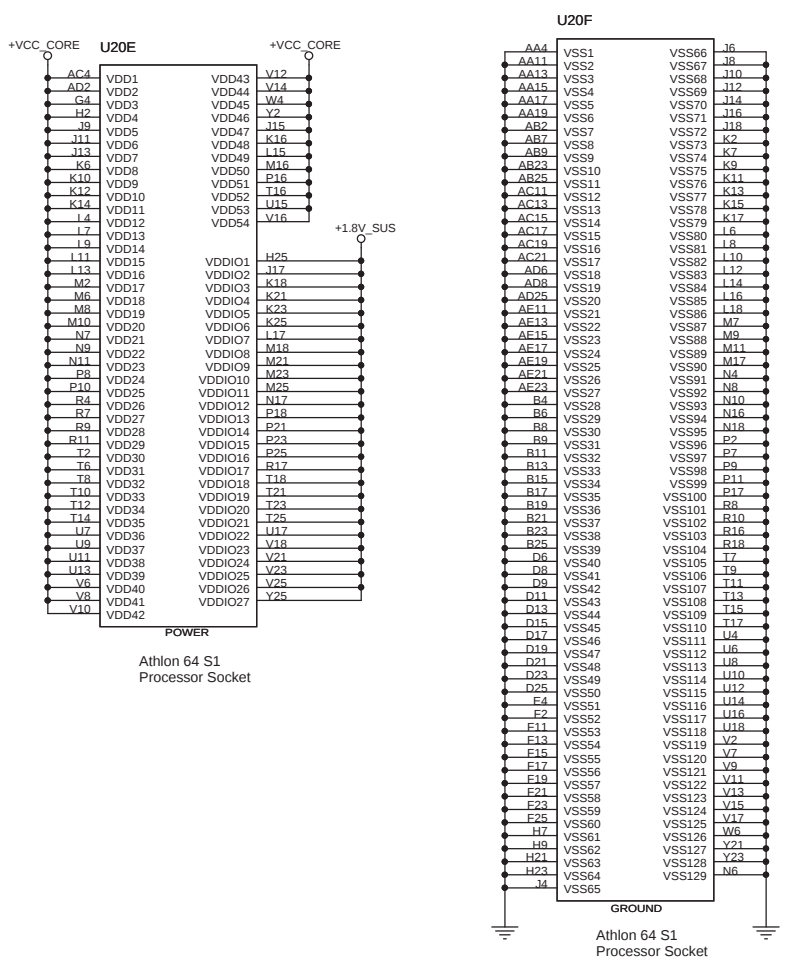
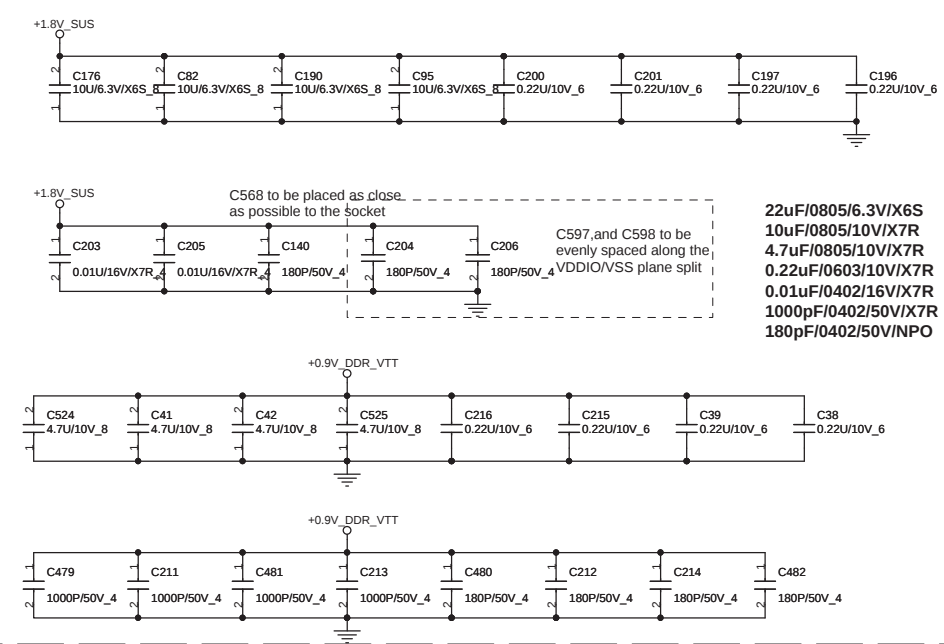
30 mil

30 mil

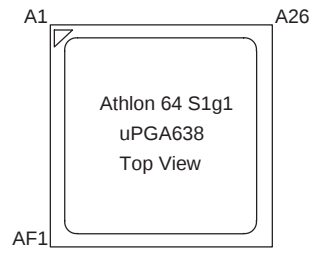
BOTTOMSIDE DECOUPLING

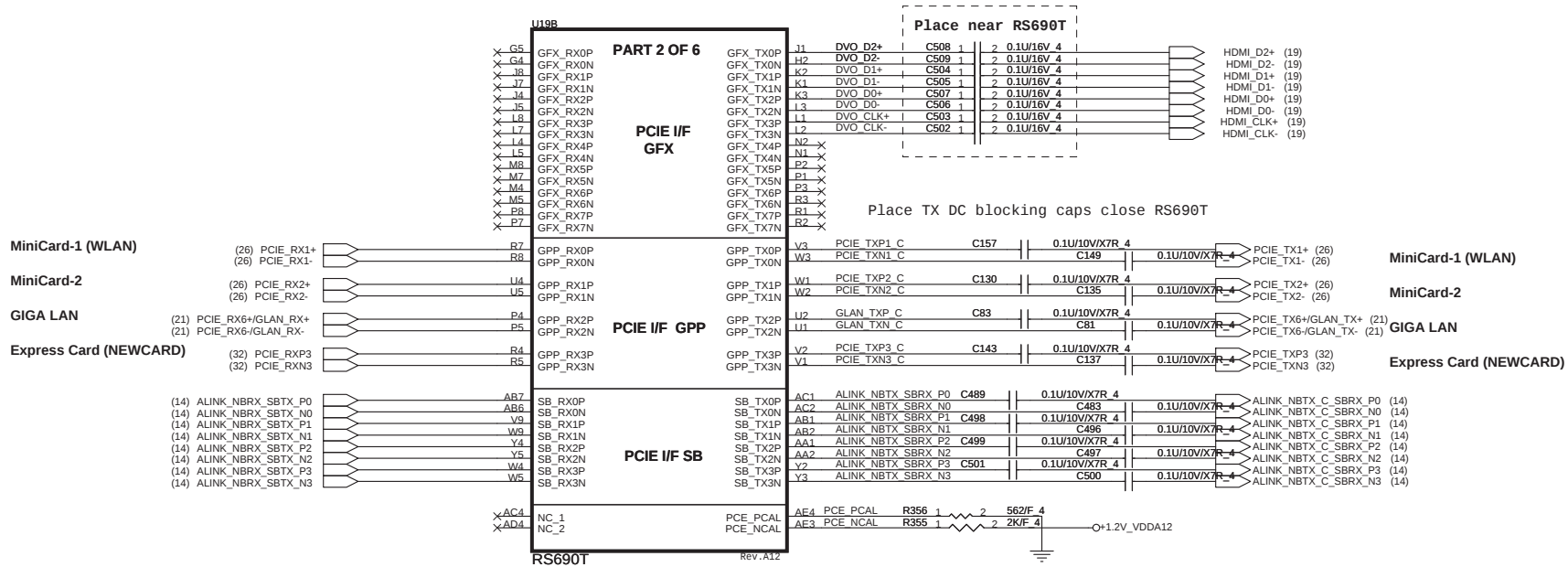


DECOUPLING BETWEEN PROCESSOR AND DIMMS PLACE CLOSE TO PROCESSOR AS POSSIBLE



PROCESSOR POWER AND GROUND





<http://hobi-elektronika.net>

<http://hobi-elektronika.net>

Power (PWR)

- AVDD1, AVDD2, AVSSN1, AVSSN2, AVDDI, AVSSDI, AVDDQ, AVSSQ, C, R, Y, G, COMP_B
- RED, GREEN, BLUE, DACVSYNC, DACHSYNC, RSET, DACSCL, DACSDA
- PLLVD18(PLLVD), PLLVSS, HTPVDD, HTPVSS
- VDDPLL_1(VDDA12), VDDPLL_2(VDDA12), VSSPLL_1(VSSA12), VSSPLL_2(VSSA12)
- LVSSR1, LVSSR3, LVSSR5, LVSSR6, LVSSR7, LVSSR8, LVSSR12, LVSSR13

Clocks (CLK)

- HTTSTCLK, HTREFCLK, TVCLKIN, OSCIN, PLLVD12(OSC), SB_CLKP, SB_CLKN
- BMREQ# D, I2C_CLK, I2C_DATA, THERMALDIODE_P, THERMALDIODE_N
- TMDS_HPD, DDC_DATA, TMDS_HPD, DDC_DATA, TESTMODE, STRP_DATA

I/O (I/O)

- TXOUT_L0P, TXOUT_L0N, TXOUT_L1P, TXOUT_L1N, TXOUT_L2P, TXOUT_L2N, TXOUT_L3P, TXOUT_L3N
- TXOUT_U0P, TXOUT_U0N, TXOUT_U1P, TXOUT_U1N, TXOUT_U2P, TXOUT_U2N, TXOUT_U3P, TXOUT_U3N
- TXCLK_LP, TXCLK_LN, TXCLK_UP, TXCLK_UN
- LVDDR18D_1, LVDDR18D_2, LVDDR33A_1, LVDDR33A_2
- LVSSR1, LVSSR3, LVSSR5, LVSSR6, LVSSR7, LVSSR8, LVSSR12, LVSSR13

MIS.

- DFT_GPIO0, DFT_GPIO1, DFT_GPIO2, DFT_GPIO3, DFT_GPIO4, DFT_GPIO5
- INT_LVDS_EDIDCLK, INT_LVDS_EDIDDATA, INT_LVDS_EDIDDATA, INT_LVDS_EDIDDATA
- INT_LVDS_EDIDCLK, INT_LVDS_EDIDDATA, INT_LVDS_EDIDDATA, INT_LVDS_EDIDDATA

Notes:

- NOTE: ACCESS TO STRAP_DATA and I2C_CLK PINS IS MANDATORY.
- RS690T
- REV.A12

Component	Value	Notes
DFT_GPIO0	Side-Port Memory Disable	PU by internal
DFT_GPIO1	By-passing EEPROM, use default values (default)	PD by external
DFT_GPIO[4:2]	Set PCI-E GPP mode to Conf. E	Side-Port Memory Enable (Default)
DFT_GPIO5	Use default values (default)	Using EEPROM Strapping
		Select PCI-E GPP mode
		Use the memory data bus for debug bus output

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Quanta Computer Inc.

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Rev: 3A

<http://hobi-elektronika.net>

Power (PWR)

- AVDD1, AVDD2, AVSSN1, AVSSN2, AVDDI, AVSSDI, AVDDQ, AVSSQ, C_R, Y_G, COMP_B
- AVDD1, AVDD2, AVSSN1, AVSSN2, AVDDI, AVSSDI, AVDDQ, AVSSQ, C_R, Y_G, COMP_B
- AVDD1, AVDD2, AVSSN1, AVSSN2, AVDDI, AVSSDI, AVDDQ, AVSSQ, C_R, Y_G, COMP_B

Clock (CLK)

- INT_CRT_RED, INT_CRT_GRN, INT_CRT_BLU, INT_VSYNC, INT_HSYNC, INT_CRT_DDCCLK, INT_CRT_DDCDAT
- INT_CRT_RED, INT_CRT_GRN, INT_CRT_BLU, INT_VSYNC, INT_HSYNC, INT_CRT_DDCCLK, INT_CRT_DDCDAT
- INT_CRT_RED, INT_CRT_GRN, INT_CRT_BLU, INT_VSYNC, INT_HSYNC, INT_CRT_DDCCLK, INT_CRT_DDCDAT

I/O (I/O)

- TXOUT_L0P, TXOUT_L0N, TXOUT_L1P, TXOUT_L1N, TXOUT_L2P, TXOUT_L2N, TXOUT_L3P, TXOUT_L3N, TXOUT_U0P, TXOUT_U0N, TXOUT_U1P, TXOUT_U1N, TXOUT_U2P, TXOUT_U2N, TXOUT_U3P, TXOUT_U3N
- TXOUT_L0P, TXOUT_L0N, TXOUT_L1P, TXOUT_L1N, TXOUT_L2P, TXOUT_L2N, TXOUT_L3P, TXOUT_L3N, TXOUT_U0P, TXOUT_U0N, TXOUT_U1P, TXOUT_U1N, TXOUT_U2P, TXOUT_U2N, TXOUT_U3P, TXOUT_U3N
- TXOUT_L0P, TXOUT_L0N, TXOUT_L1P, TXOUT_L1N, TXOUT_L2P, TXOUT_L2N, TXOUT_L3P, TXOUT_L3N, TXOUT_U0P, TXOUT_U0N, TXOUT_U1P, TXOUT_U1N, TXOUT_U2P, TXOUT_U2N, TXOUT_U3P, TXOUT_U3N

MIS.

- INT_LVDS_EDIDCLK, INT_LVDS_EDIDDATA, INT_LVDS_BLEN, INT_LVDS_BLOK, INT_LVDS_BLOK, INT_LVDS_BLOK, INT_LVDS_BLOK
- INT_LVDS_EDIDCLK, INT_LVDS_EDIDDATA, INT_LVDS_BLEN, INT_LVDS_BLOK, INT_LVDS_BLOK, INT_LVDS_BLOK, INT_LVDS_BLOK
- INT_LVDS_EDIDCLK, INT_LVDS_EDIDDATA, INT_LVDS_BLEN, INT_LVDS_BLOK, INT_LVDS_BLOK, INT_LVDS_BLOK, INT_LVDS_BLOK

Table 1: Component Values

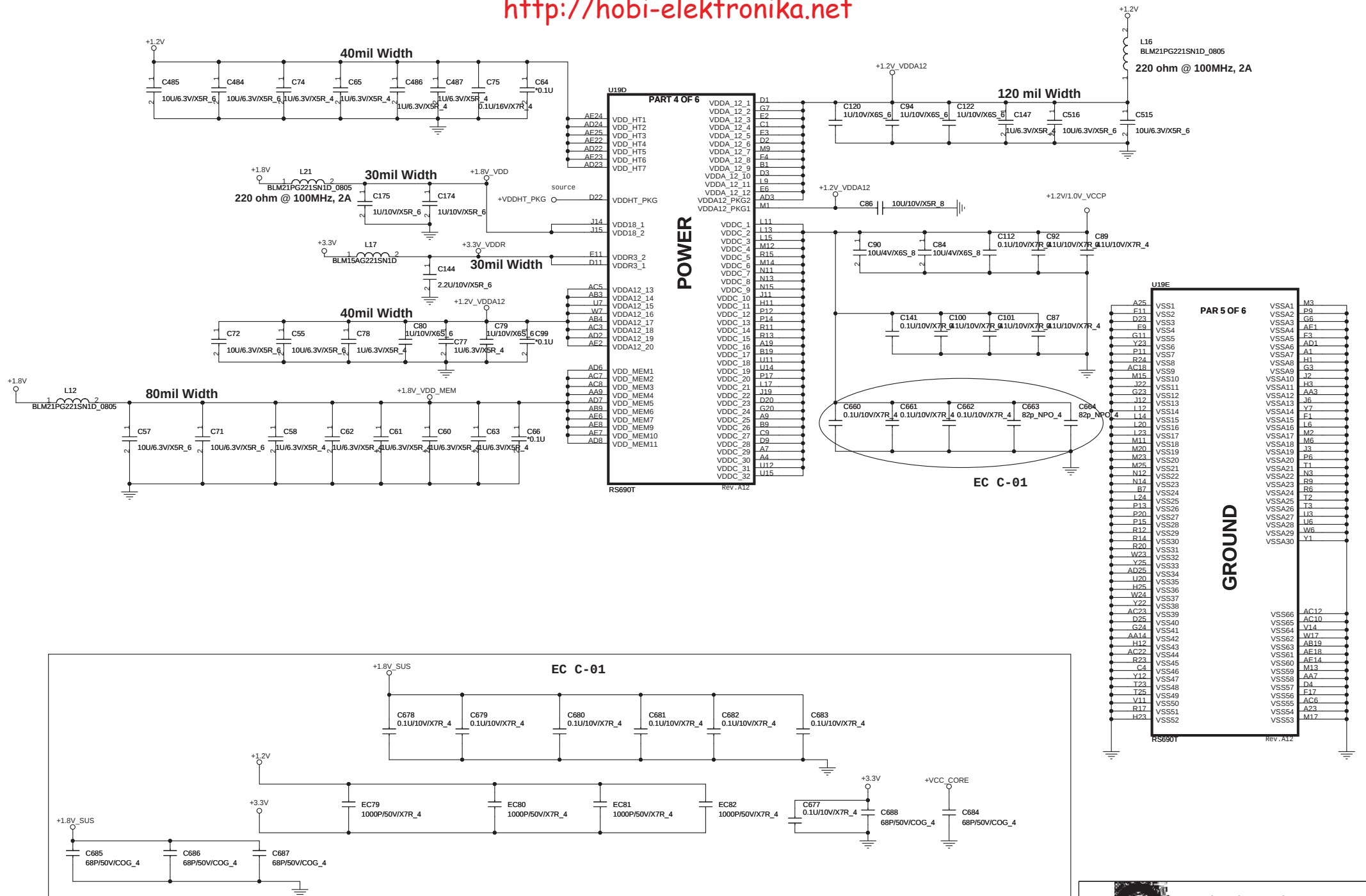
Component	Value
C181	2.2U/10V_6
C188	0.1U/16V_4
C193	0.01U
R363	10K_4
R364	4.7K
R365	10K_4
R366	4.7K
R367	10K_4
R368	10K_4
R369	10K_4
R370	10K_4
R371	4.7K
R372	10K_4
R373	10K_4
R374	10K_4
R375	10K_4
R376	10K_4
R377	10K_4
R378	10K_4
R379	10K_4
R380	10K_4
R381	10K_4
R382	10K_4
R383	10K_4
R384	10K_4
R385	10K_4
R386	10K_4
R387	10K_4
R388	10K_4
R389	10K_4
R390	10K_4
R391	10K_4
R392	10K_4
R393	10K_4
R394	10K_4
R395	10K_4
R396	10K_4
R397	10K_4
R398	10K_4
R399	10K_4
R400	10K_4

Table 2: Component Values

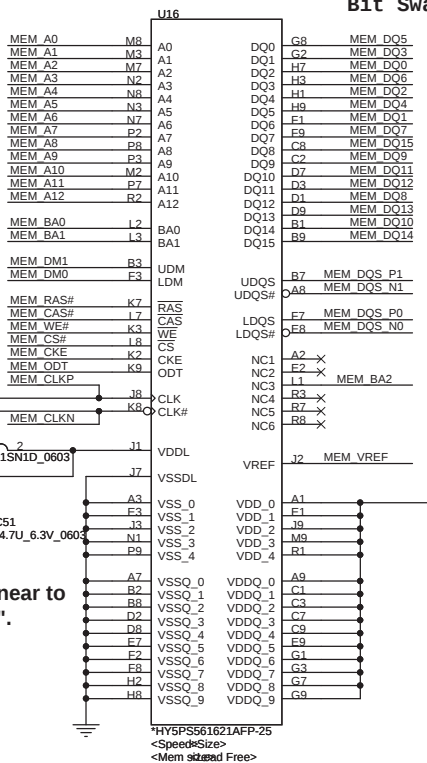
Component	Value
C181	2.2U/10V_6
C188	0.1U/16V_4
C193	0.01U
R363	10K_4
R364	4.7K
R365	10K_4
R366	4.7K
R367	10K_4
R368	10K_4
R369	10K_4
R370	10K_4
R371	4.7K
R372	10K_4
R373	10K_4
R374	10K_4
R375	10K_4
R376	10K_4
R377	10K_4
R378	10K_4
R379	10K_4
R380	10K_4
R381	10K_4
R382	10K_4
R383	10K_4
R384	10K_4
R385	10K_4
R386	10K_4
R387	10K_4
R388	10K_4
R389	10K_4
R390	10K_4
R391	10K_4
R392	10K_4
R393	10K_4
R394	10K_4
R395	10K_4
R396	10K_4
R397	10K_4
R398	10K_4
R399	10K_4
R400	10K_4

Table 3: Component Values

Component	Value
C181	2.2U/10V_6
C188	0.1U/16V_4
C193	0.01U
R363	10K_4
R364	4.7K
R365	10K_4
R366	4.7K
R367	10K_4
R368	10K_4
R369	10K_4
R370	10K_4
R371	4.7K
R372	10K_4
R373	10K_4
R374	10K_4
R375	10K_4
R376	10K_4
R377	10K_4
R378	10K_4
R379	10K_4
R380	10K_4
R381	10K_4
R382	10K_4
R383	10K_4



Bit Swap

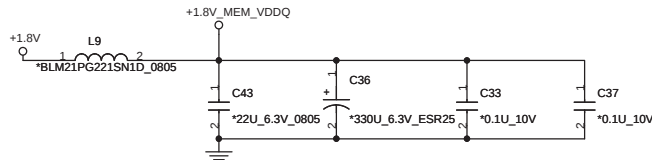
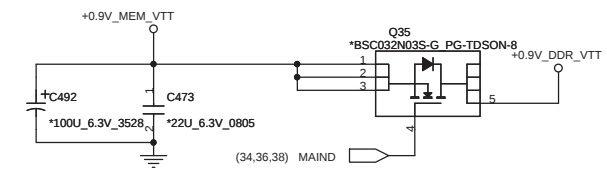
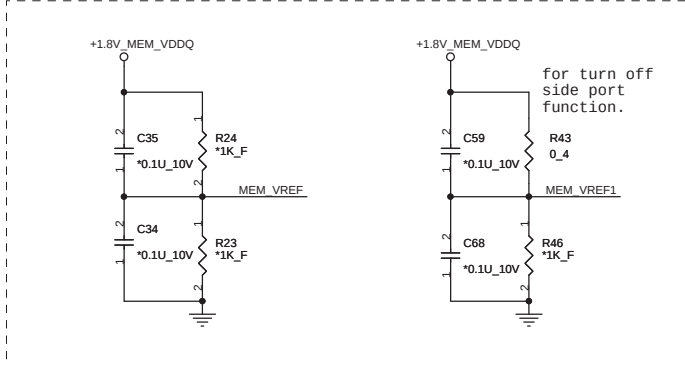


Place R504 to close to U5.



Place This CAP near to SDRAM with 0.2".

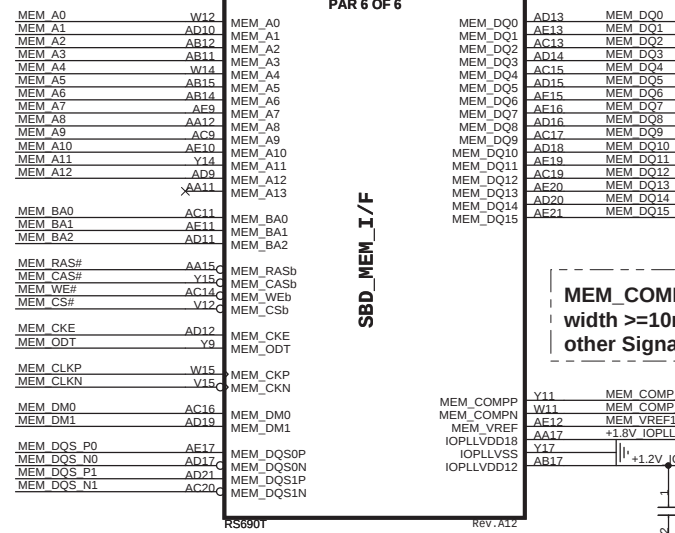
256-Mbit DDR2 16Mbit*16(4bank)



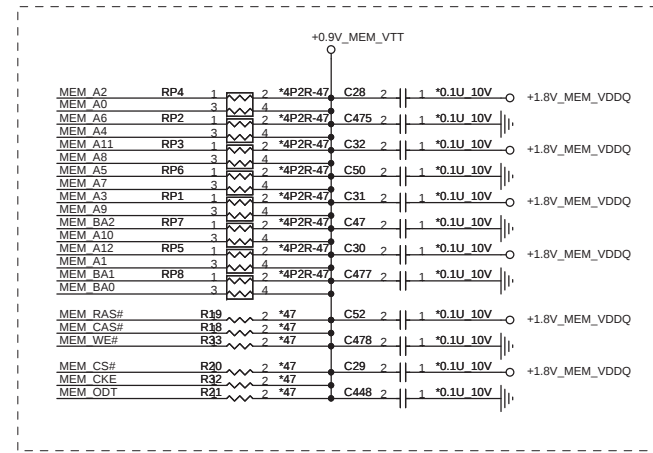
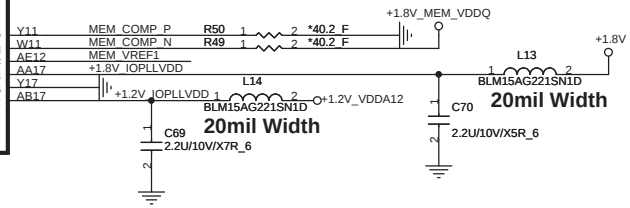
Local Frame Buffer(64MB) DDRII Power

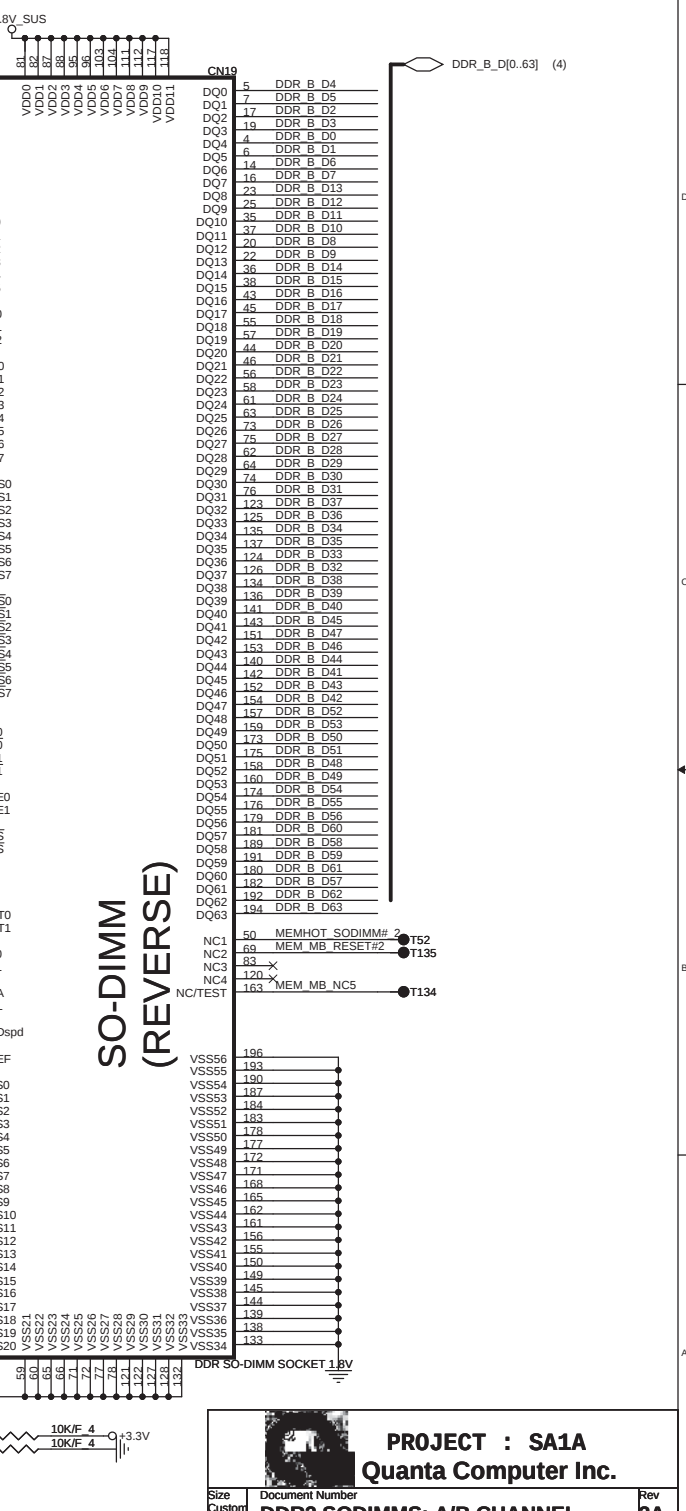
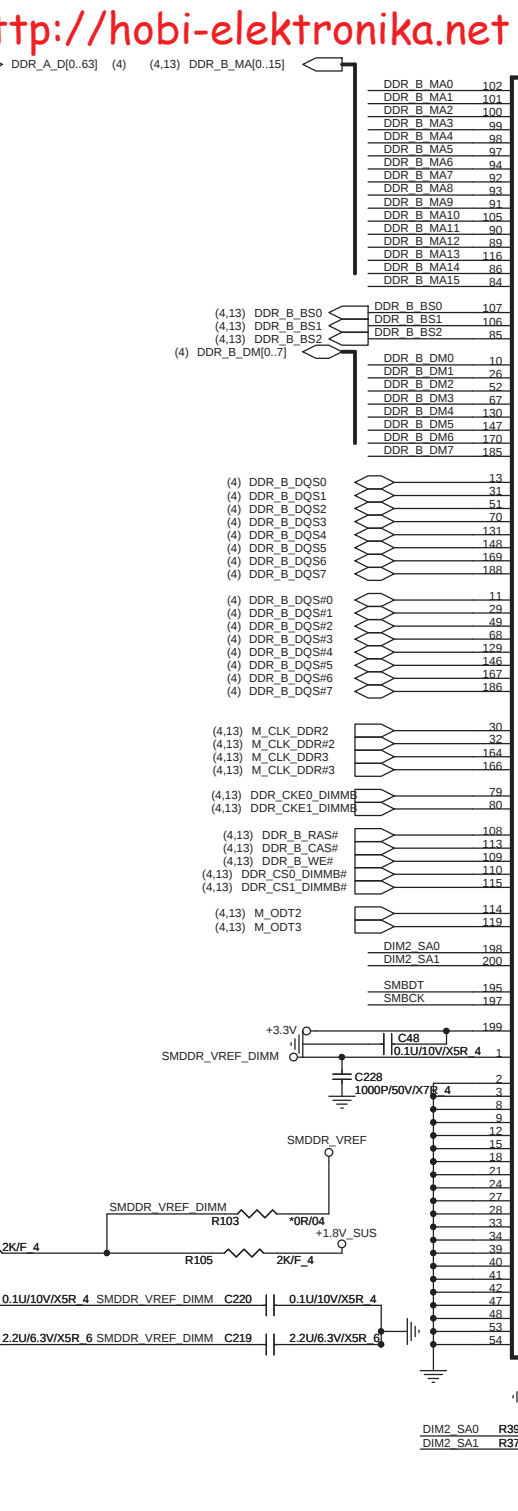
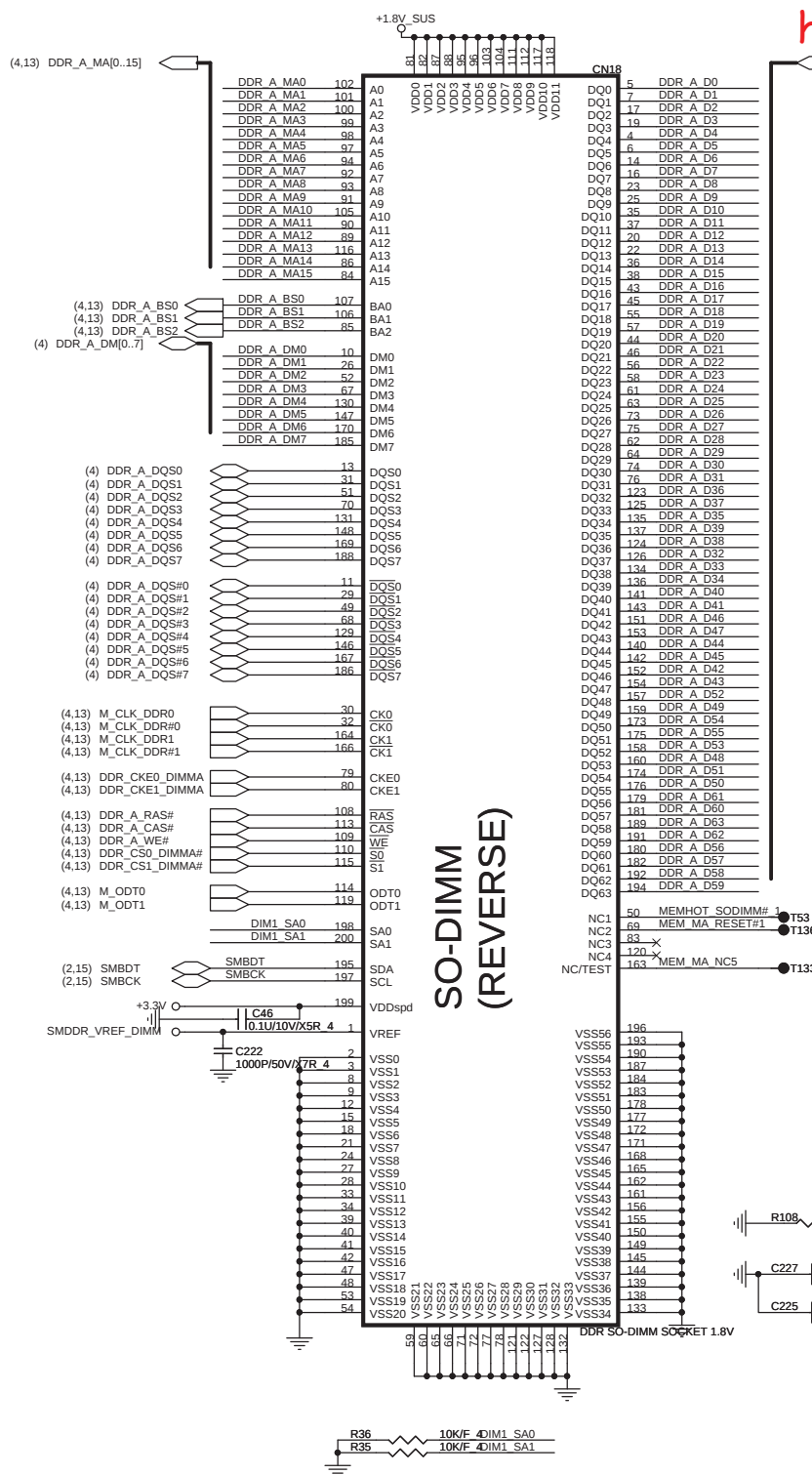
Local Frame Buffer(64MB) DDRII Power

SBD_MEM_I/F



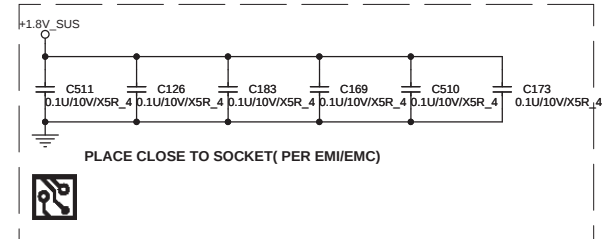
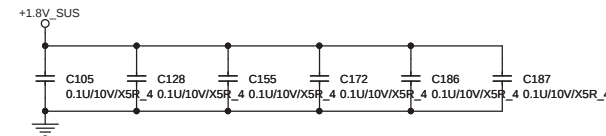
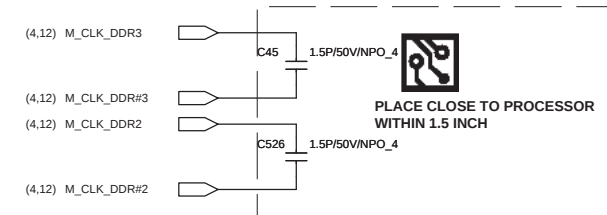
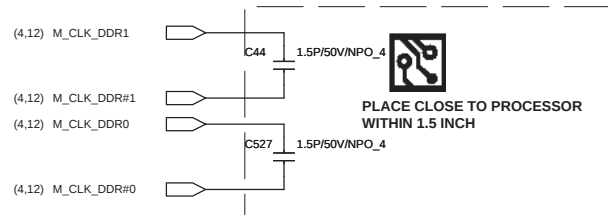
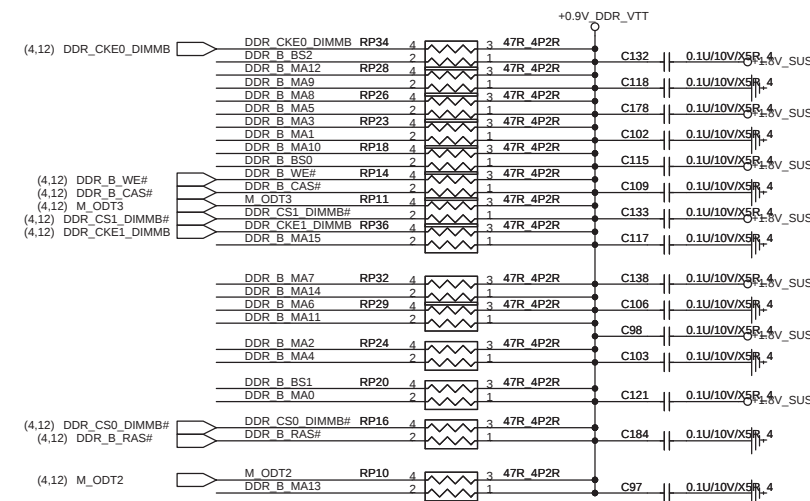
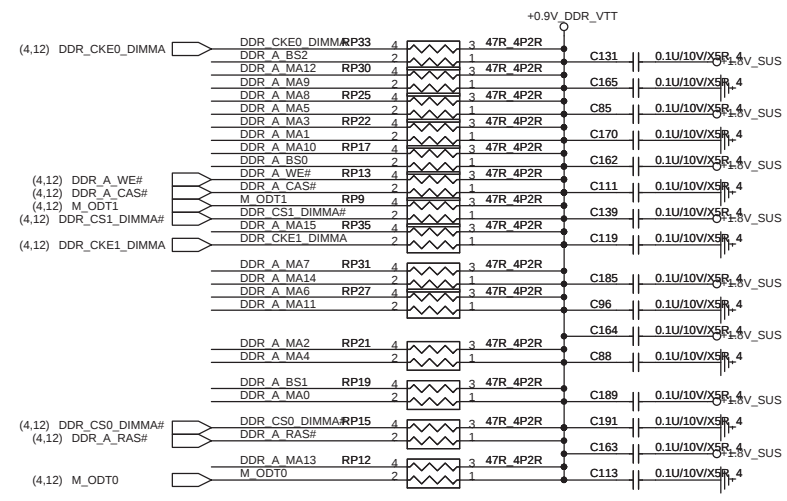
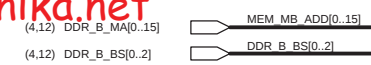
MEM_COMP_P and MEM_COMP_N trace width >=10mils and 10mils spacing from other Signals in X,Y,Z directions

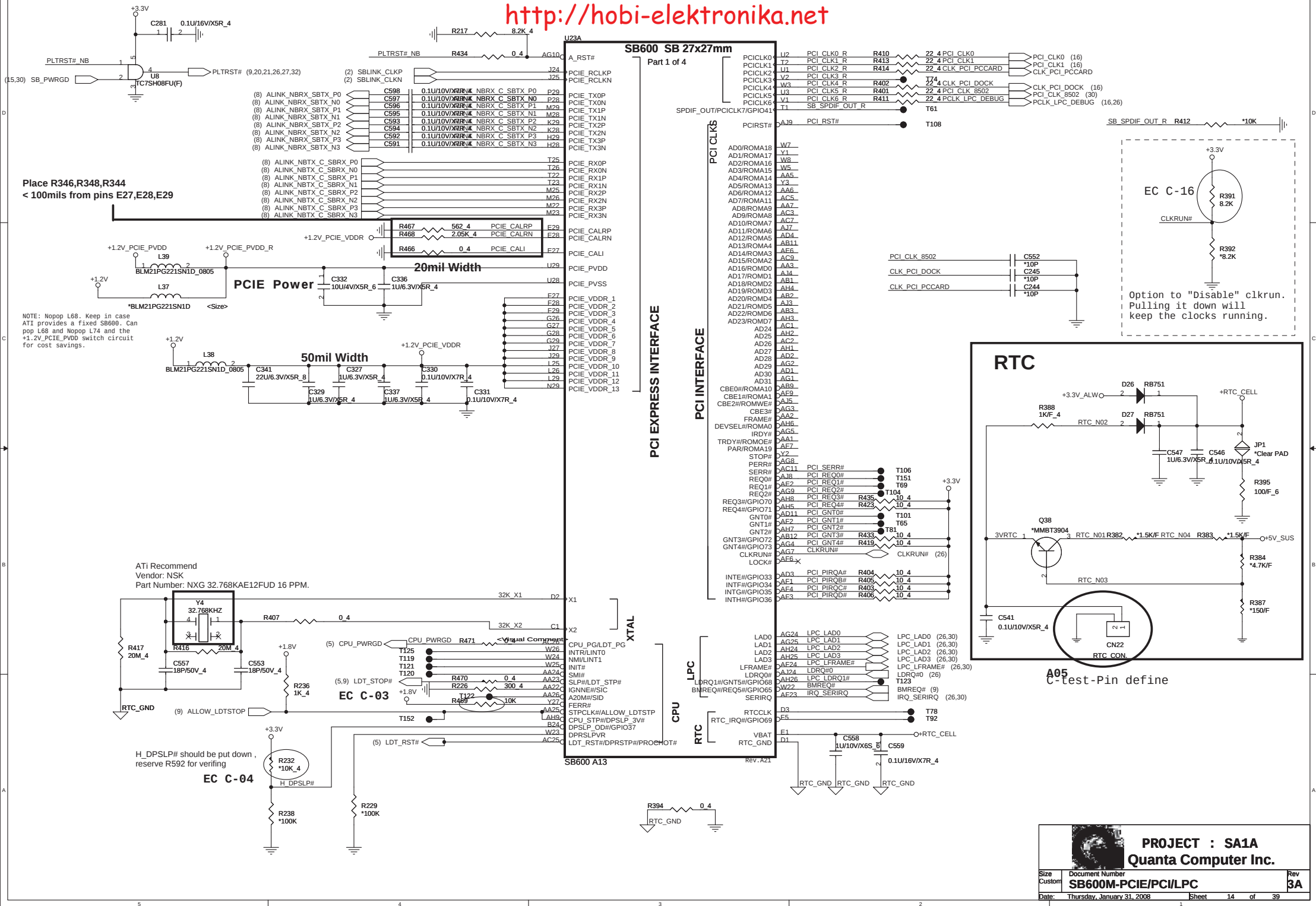


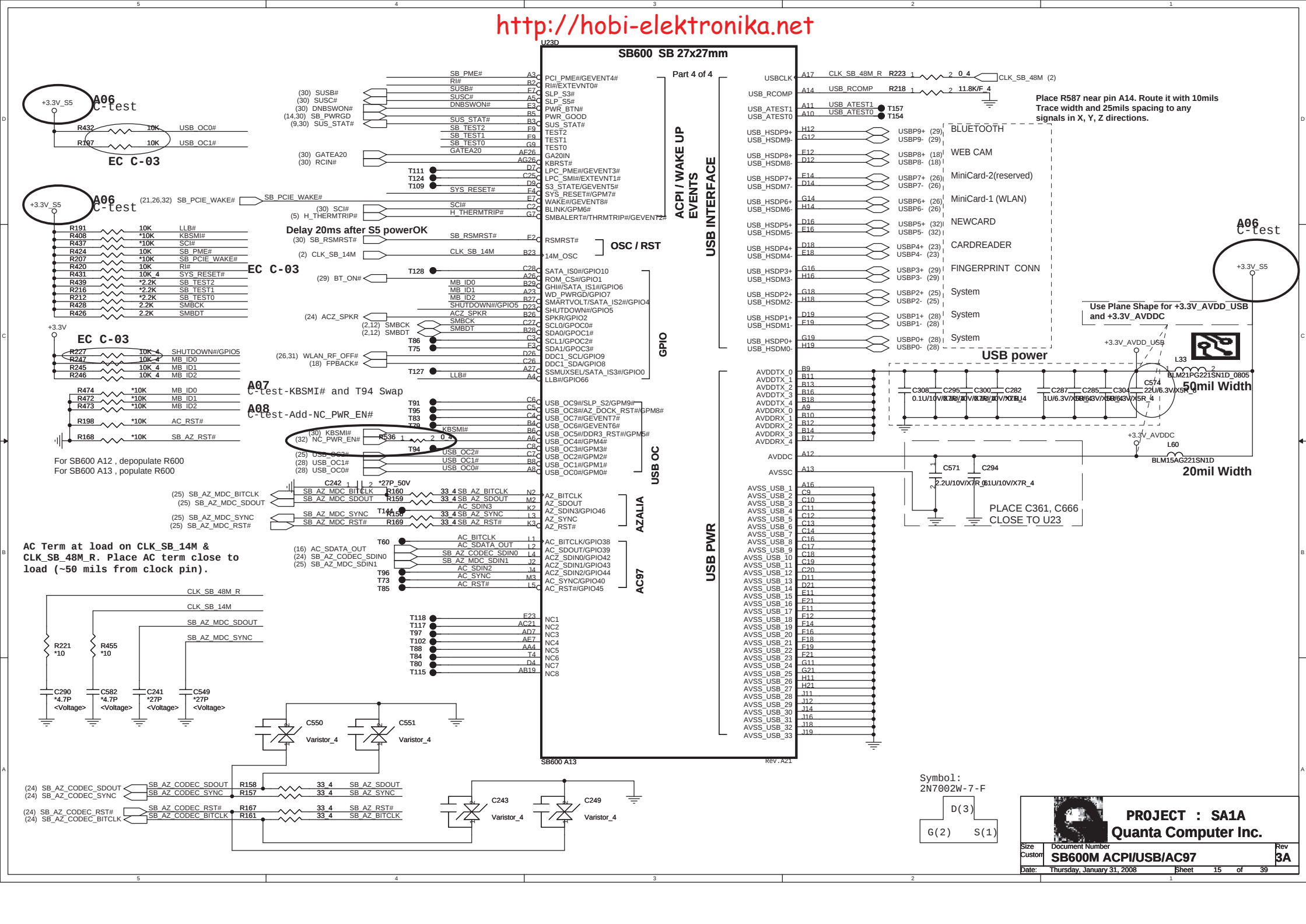


PROJECT : SA1A
Quanta Computer Inc.

Size: Custom
Document Number: 3A
Date: Thursday, January 31, 2008
Sheet 12 of 39

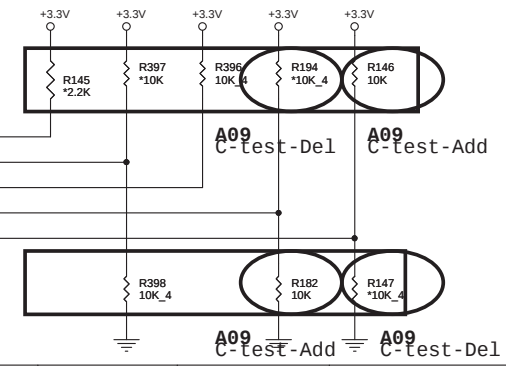






REQUIRED STRAPS

15K internal PU for RTC_CLK
, External PU/PD is not required.
SB600 has 15K internal PD for AC_SDOUT

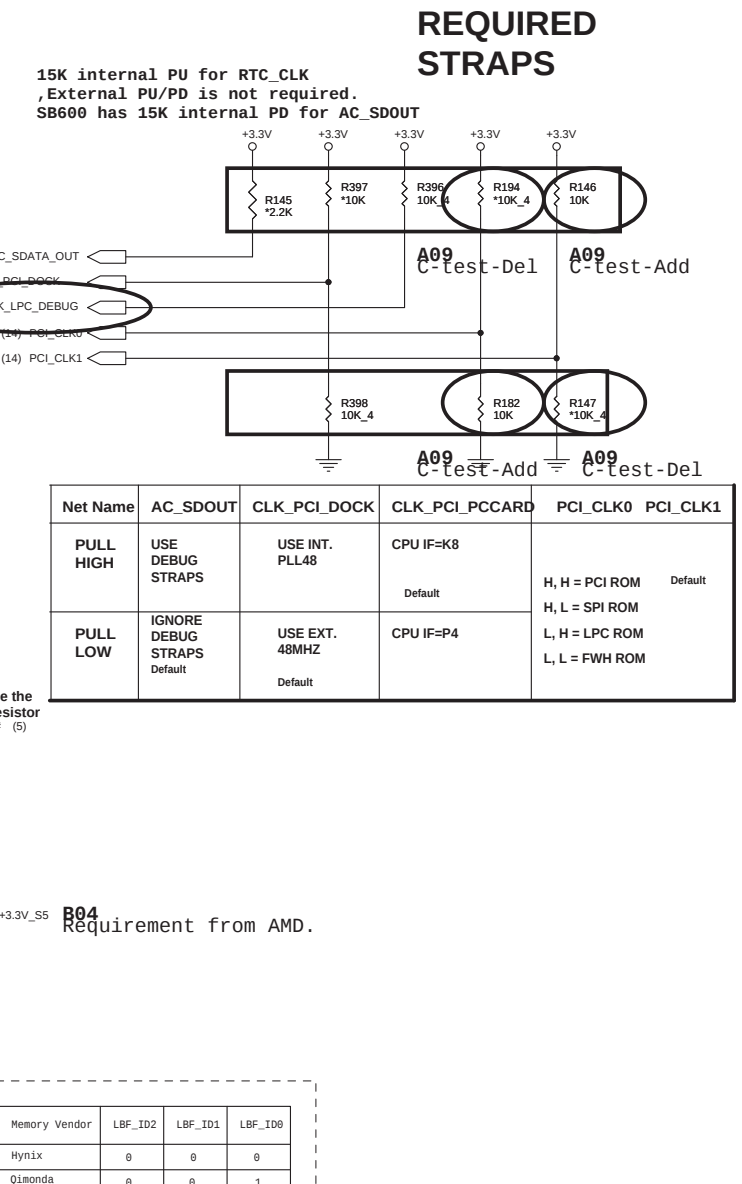
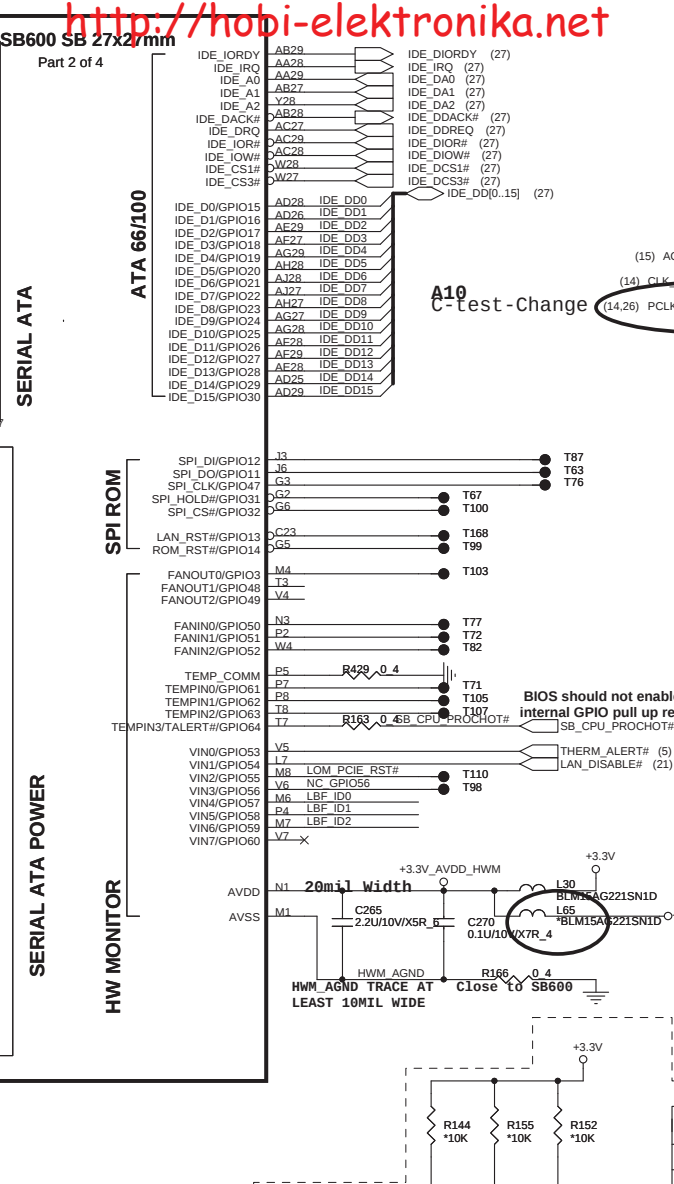
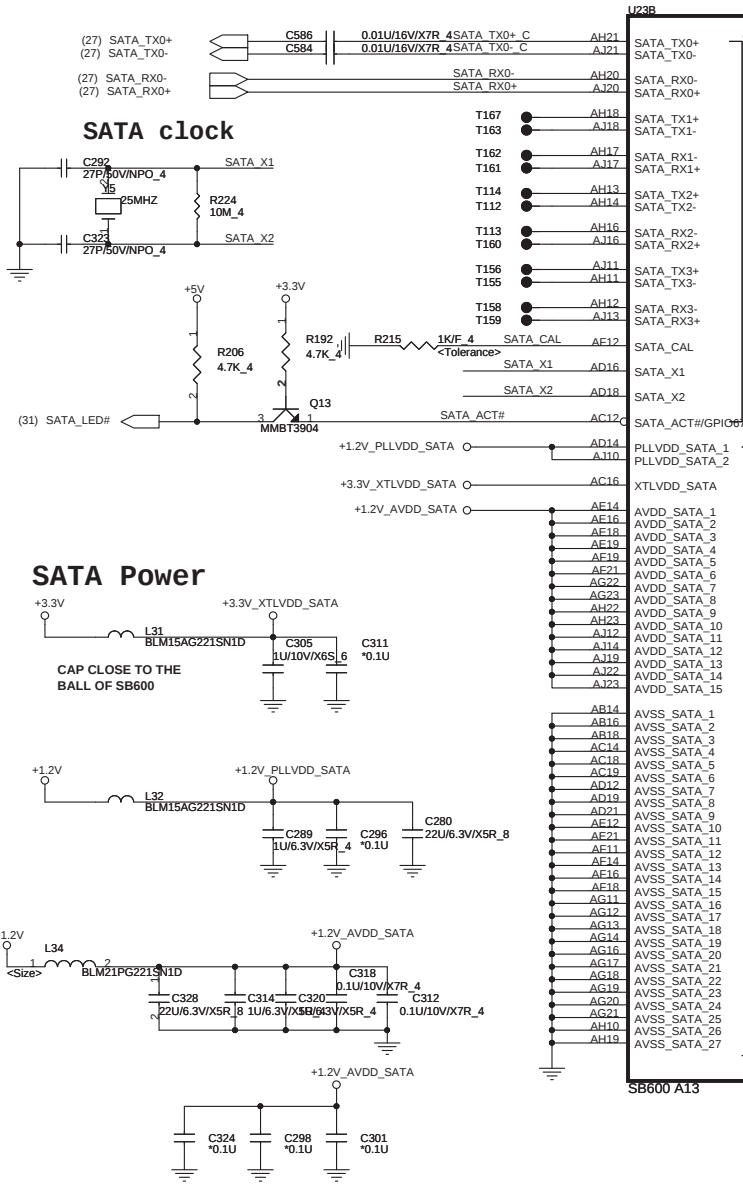


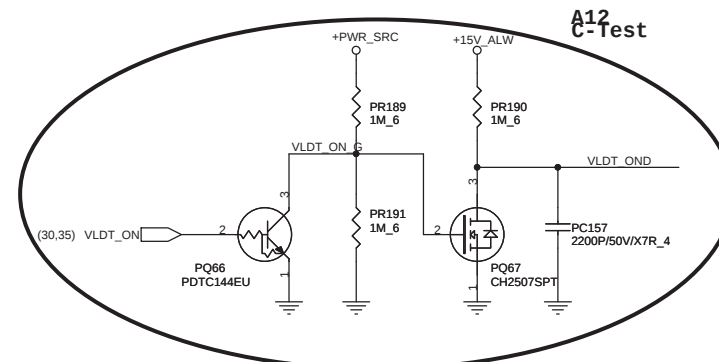
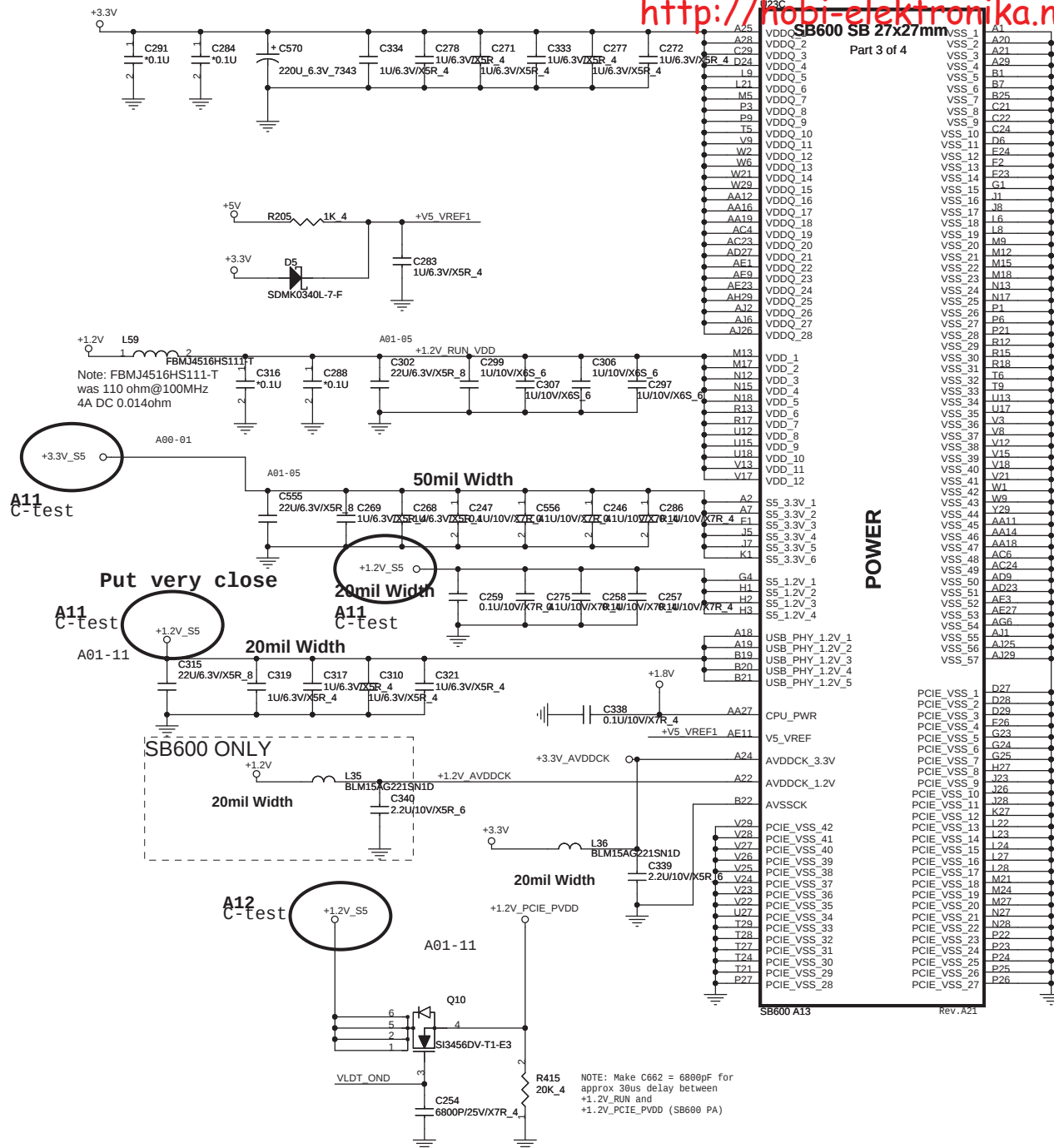
Net Name	AC_SDOUT	CLK_PCI_DOCK	CLK_PCI_PCCARD	PCI_CLK0	PCI_CLK1
PULL HIGH	USE DEBUG STRAPS	USE INT. PLL48	CPU IF=K8	H, H = PCI ROM H, L = SPI ROM	Default
PULL LOW	IGNORE DEBUG STRAPS	USE EXT. 48MHZ	CPU IF=P4	L, H = LPC ROM L, L = FWH ROM	

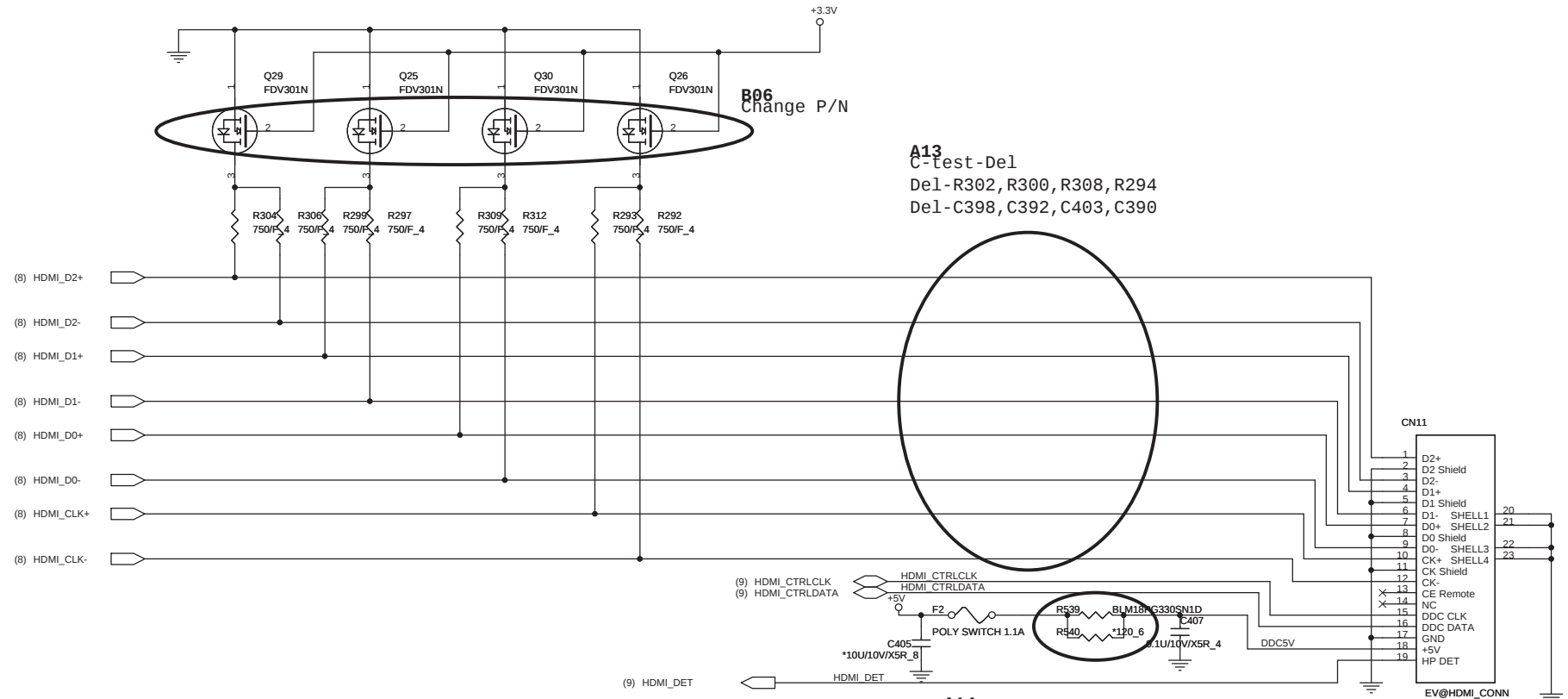
B04 Requirement from AMD.

Memory Vendor	LBF_ID2	LBF_ID1	LBF_ID0
Hynix	0	0	0
Qimonda	0	0	1
Samsung	0	1	0

NC GPIO56	R162	*20K
THERM_ALERT#	R202	*20K
LAN_DISABLE#	R208	*20K
LOM_PCIE_RST#	R214	*20K







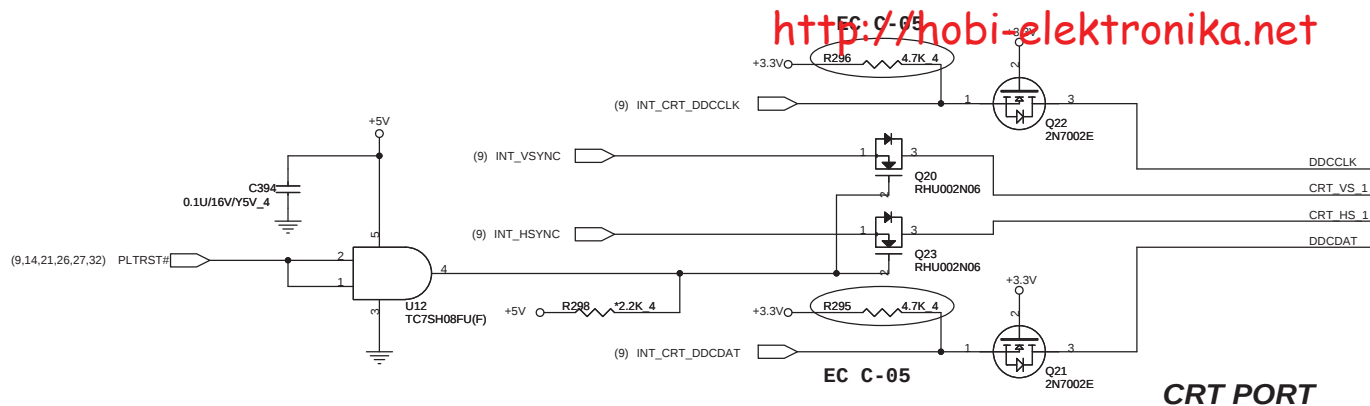
B06
Change P/N

A13
C-test-Del
Del-R302, R300, R308, R294
Del-C398, C392, C403, C390

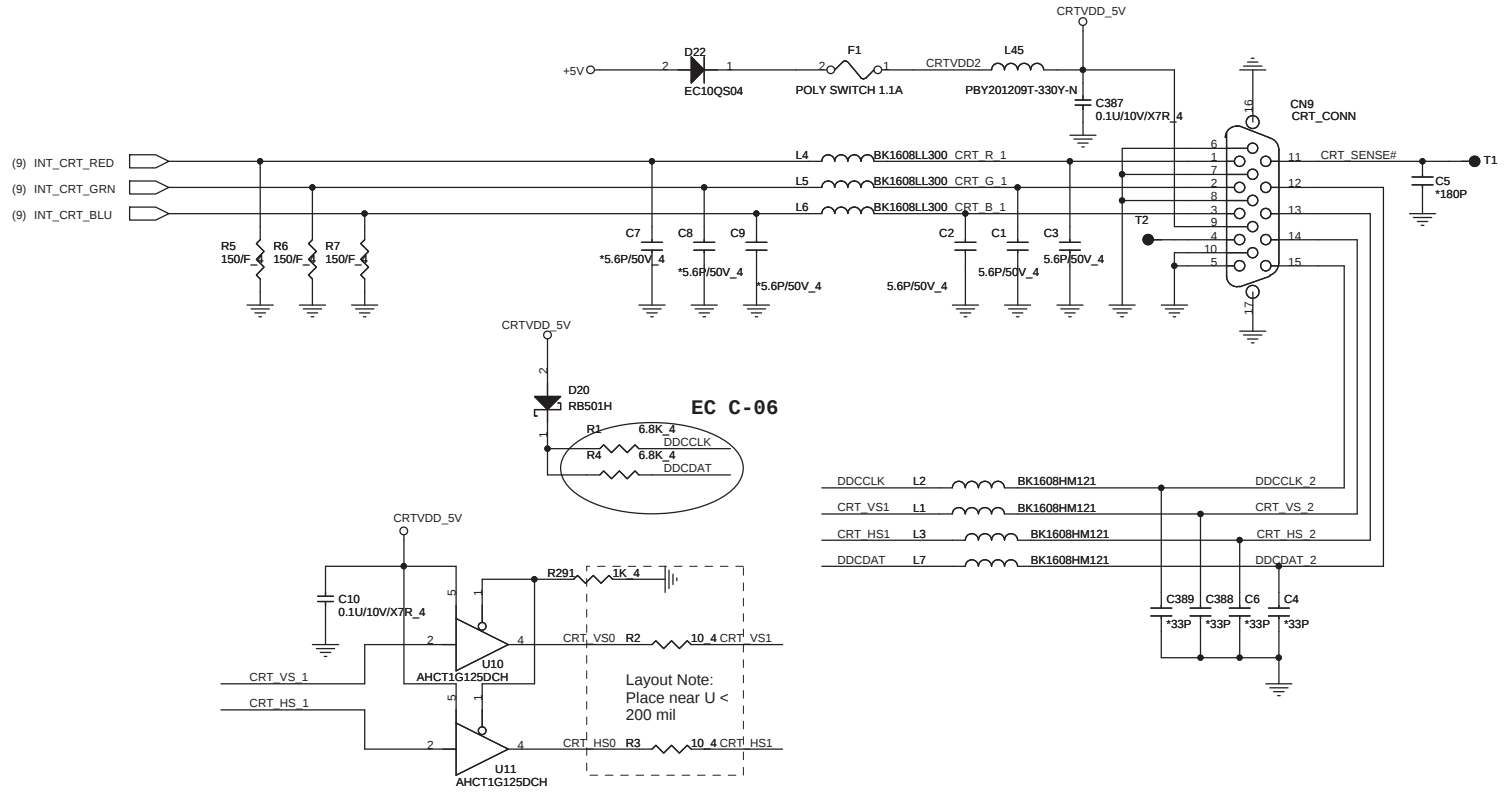
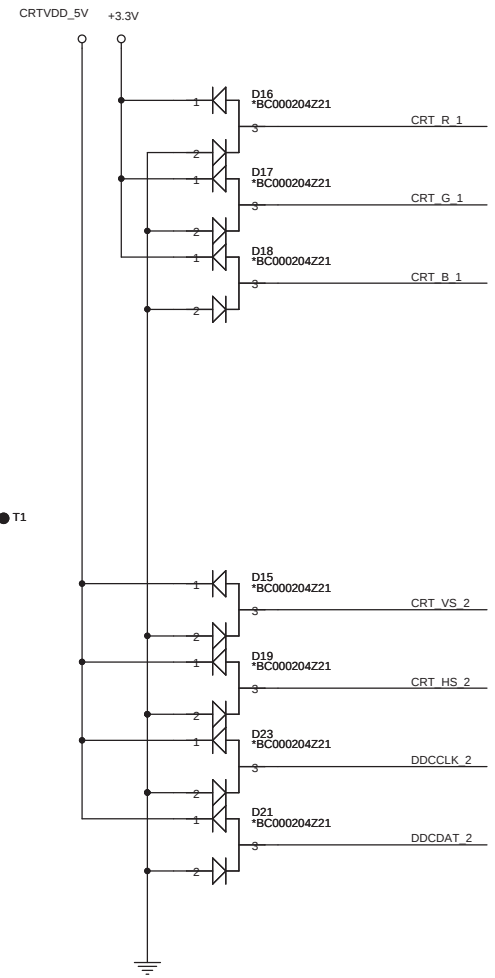
A14
C-test-120//120=60 Ohm
EC C-12

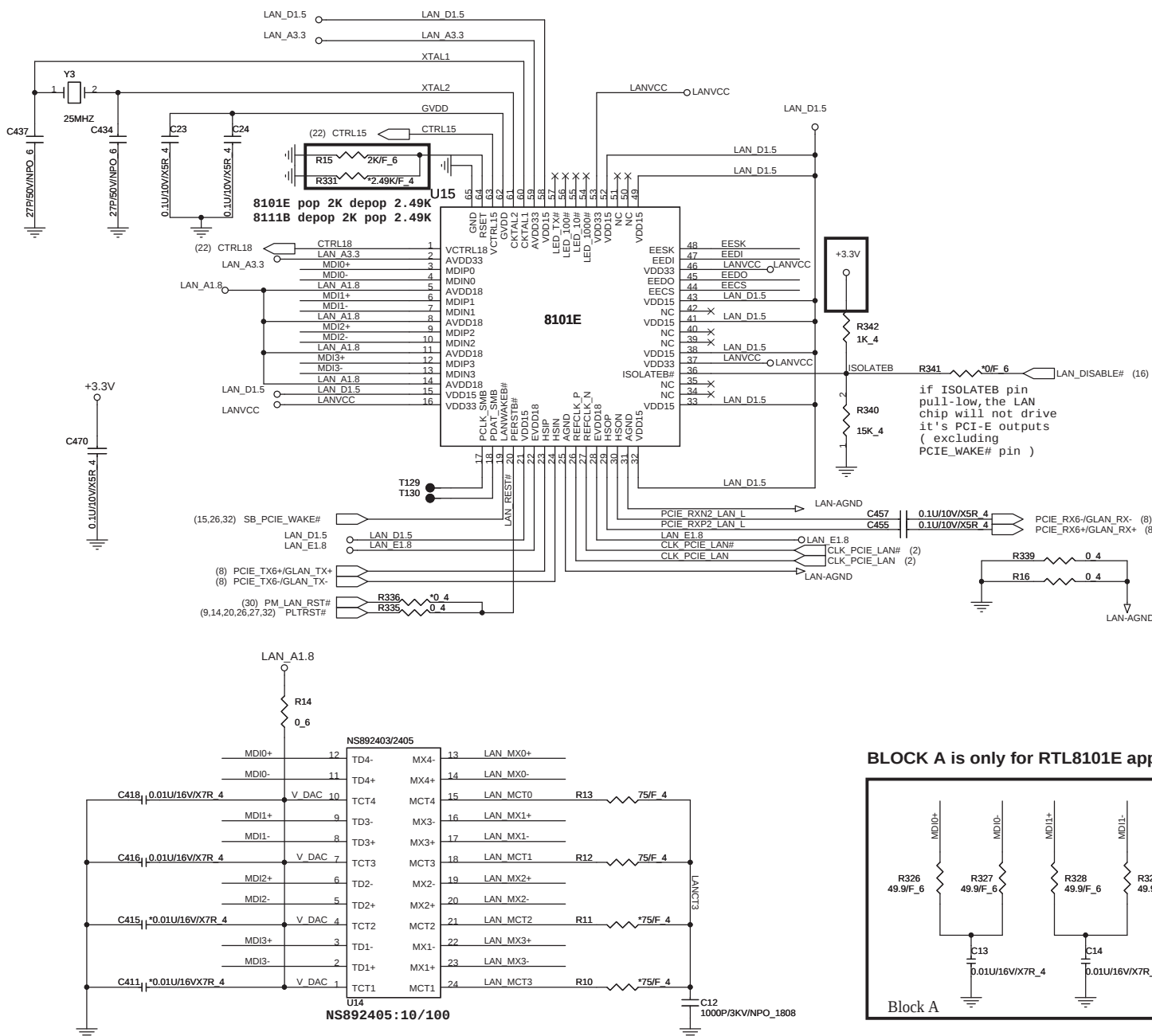
LAYOUT must support
connectors from JAE,
Molex, and Acon

LANCELOT

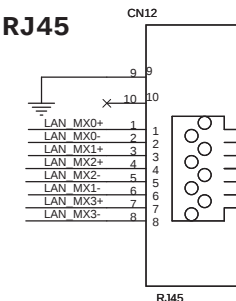


ESD PORTECTION

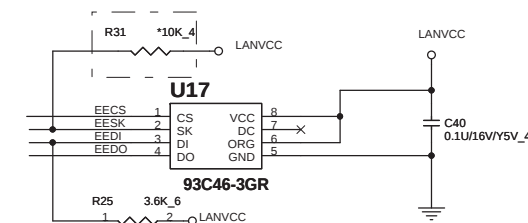




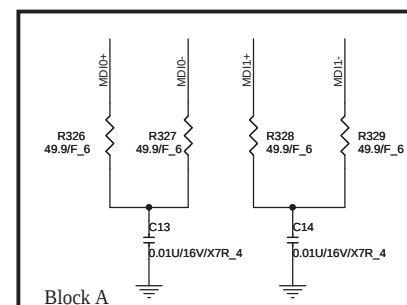
RJ45



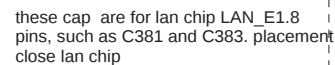
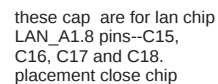
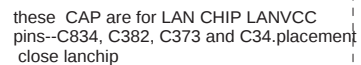
for 93C56 used. NC if 93C46 is used.



BLOCK A is only for RTL8101E application.

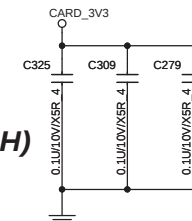


	10/100M	1G
R14 R15 R16 R17	ASM	NoASM



	RTL8111B / RTL8101E	
LANVCC	3.3V	
LAN_D1.8	1.8V	
LAN_A1.8	1.8V	
LAN_D1.5	1.5V	

	Q23	Q24
RTL8111B	<i>Need</i>	<i>Need</i>
RTL8101E	<i>N/A</i>	<i>N/A</i>



Support SD/MS/xD/SM/RS-MMC/MMC/miniSD Cards

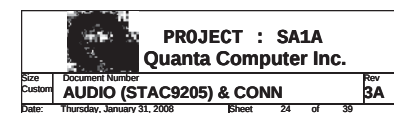
[illegible]

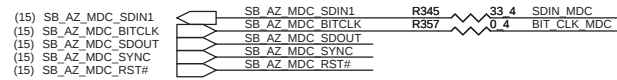
A17
C-test-De1



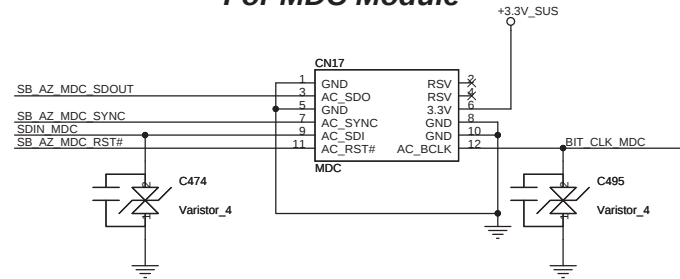
PROJECT : SA1A
Quanta Computer Inc.

Rev
3A

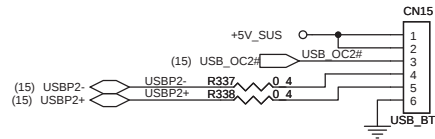


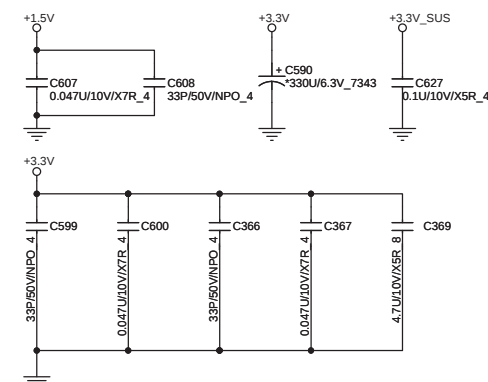
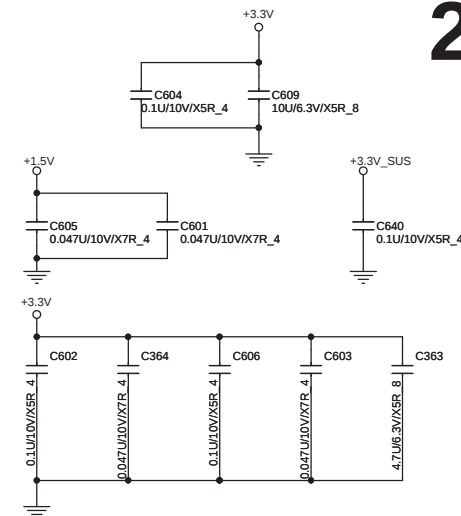


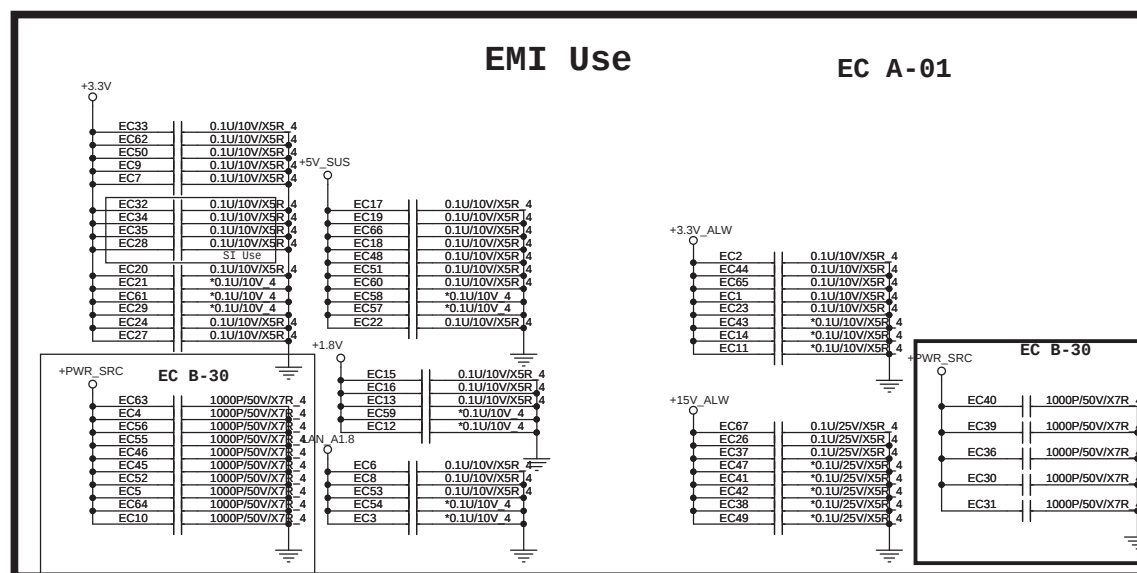
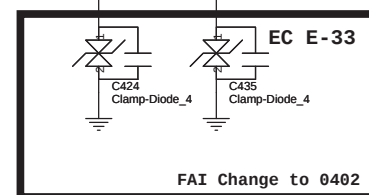
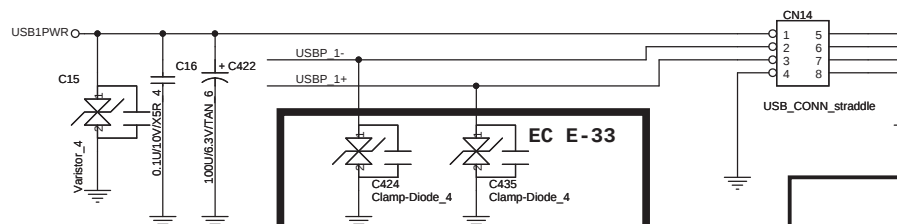
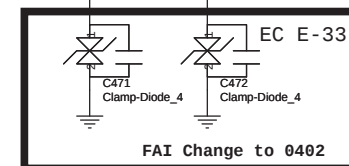
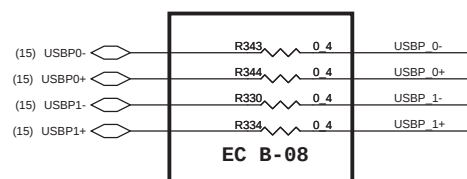
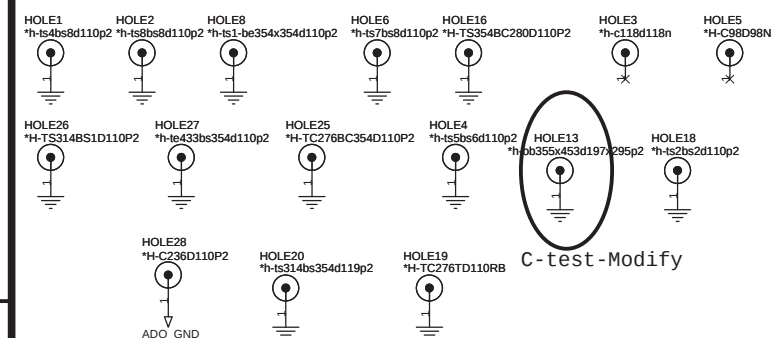
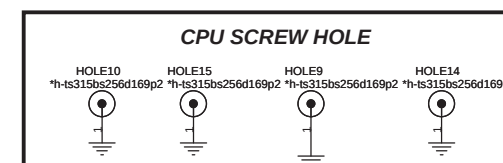
For MDC Module

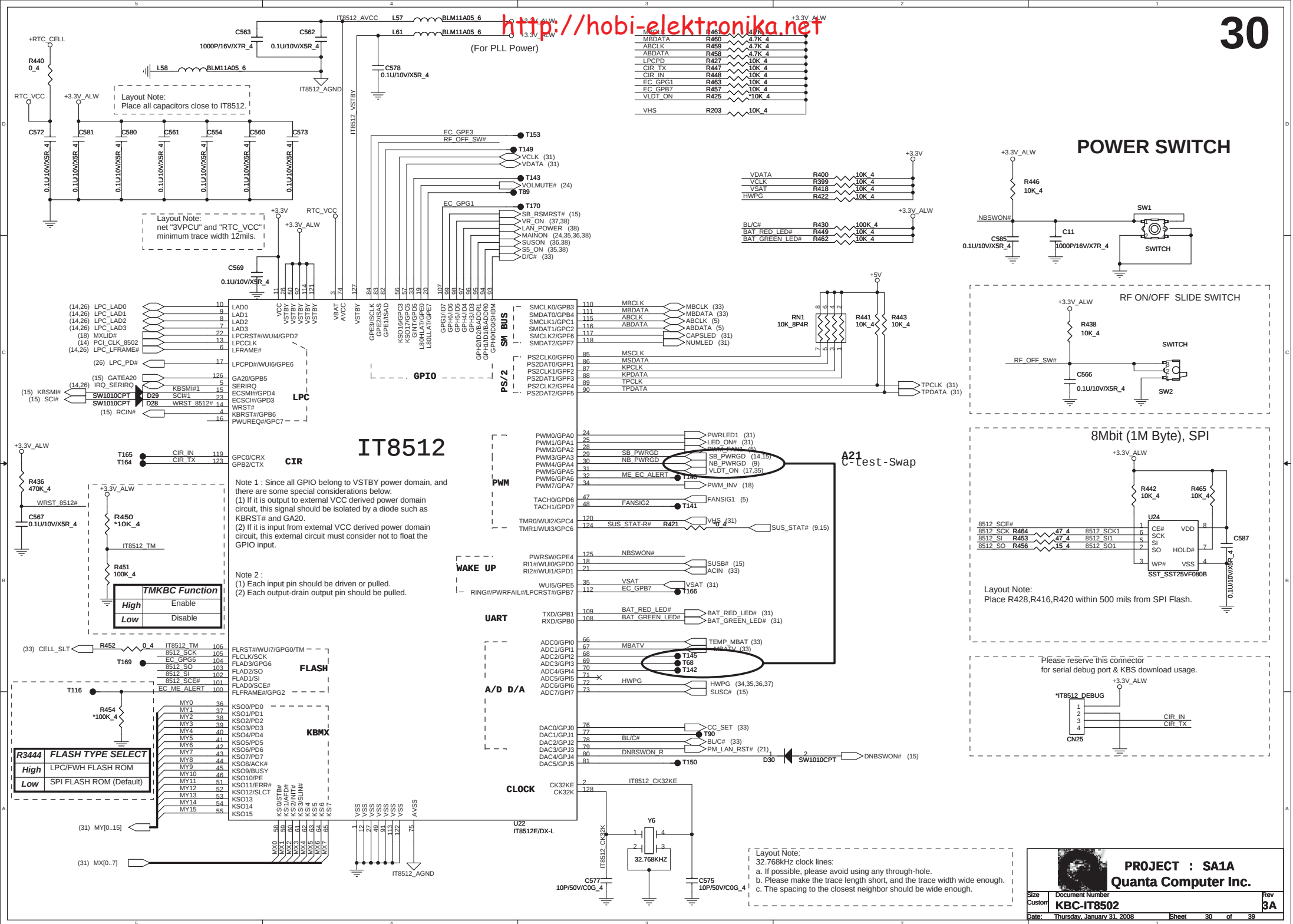


TO RJ11/USB PORT

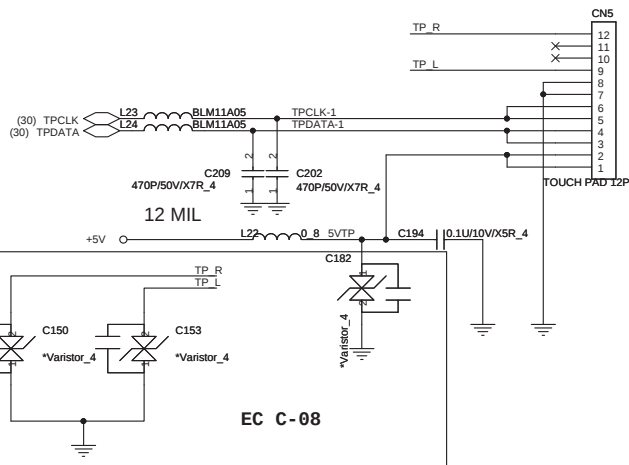
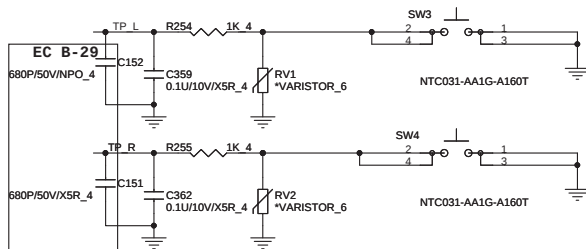






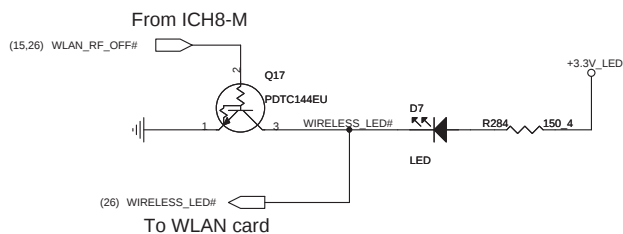


TOUCHPAD SWITCH CONN



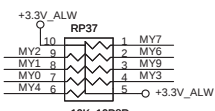
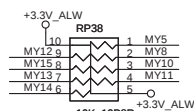
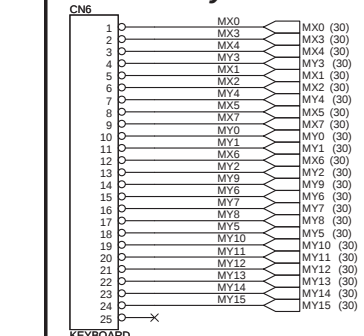
EC C-08

WIRELESS LED

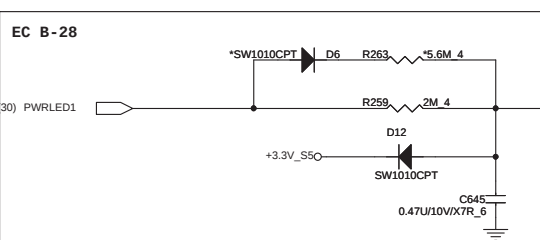
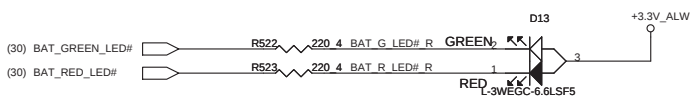
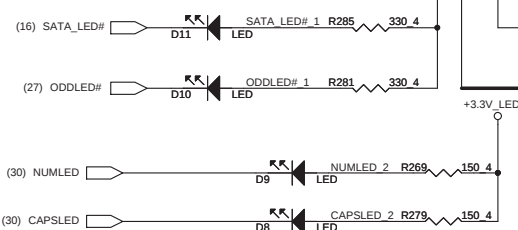


<http://hobi-elektronika.net>

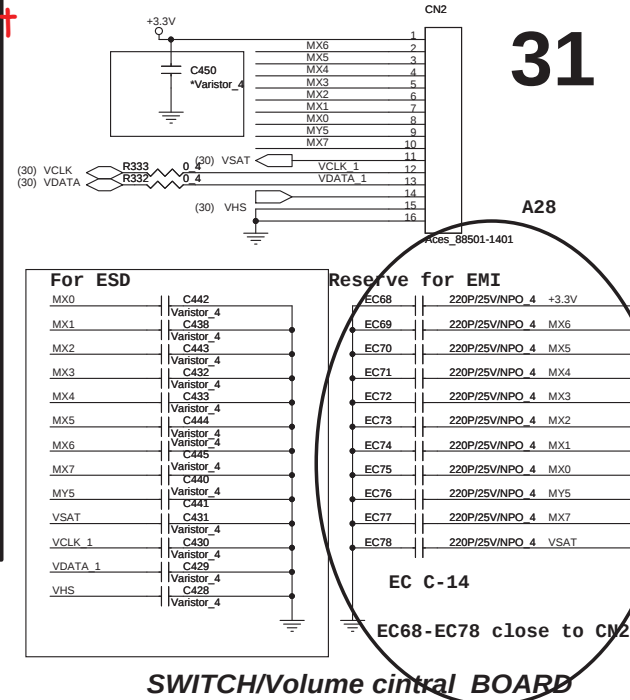
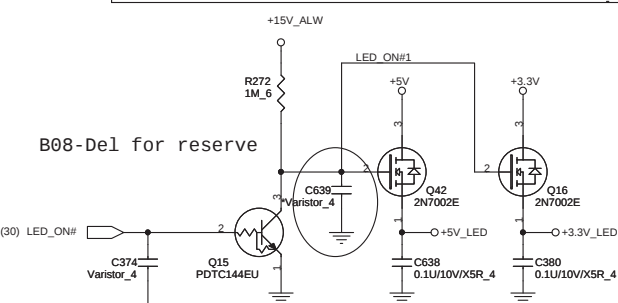
KEYBOARD For New Keyboard use.



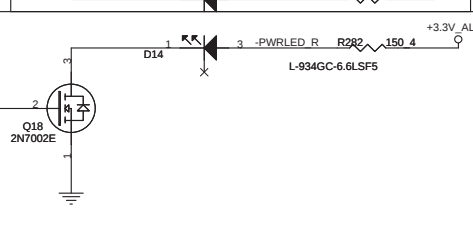
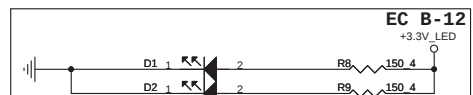
LED INDICATOR



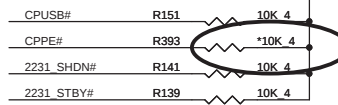
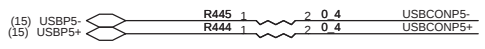
B08-De1 for reserve



SWITCH/Volume cintral BOARD



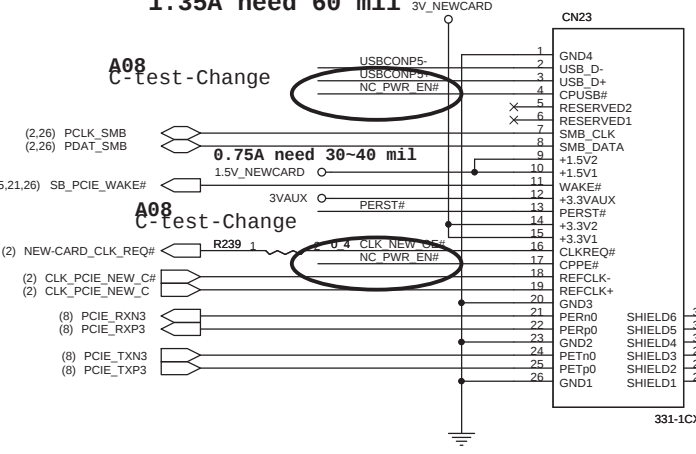
NEWCARD



A08
C-test-Del

1.35A need 60 mil

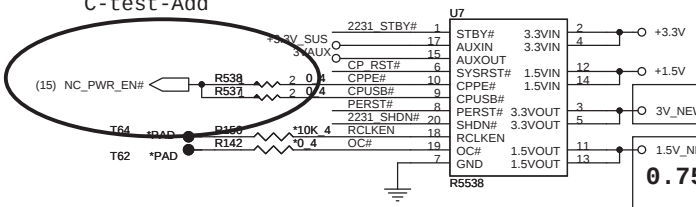
A08
C-test-Change



0.75A need 30~40 mil

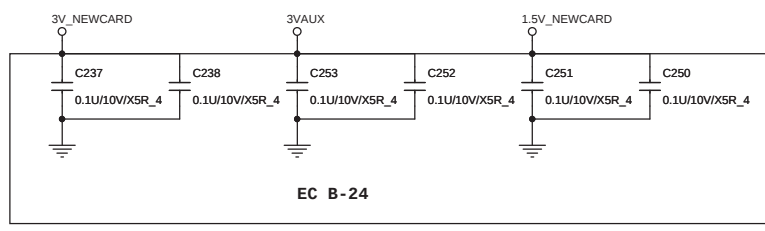
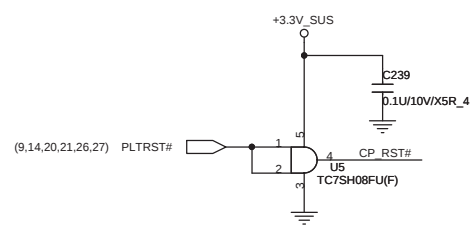
A08
C-test-Change

A08
C-test-Add

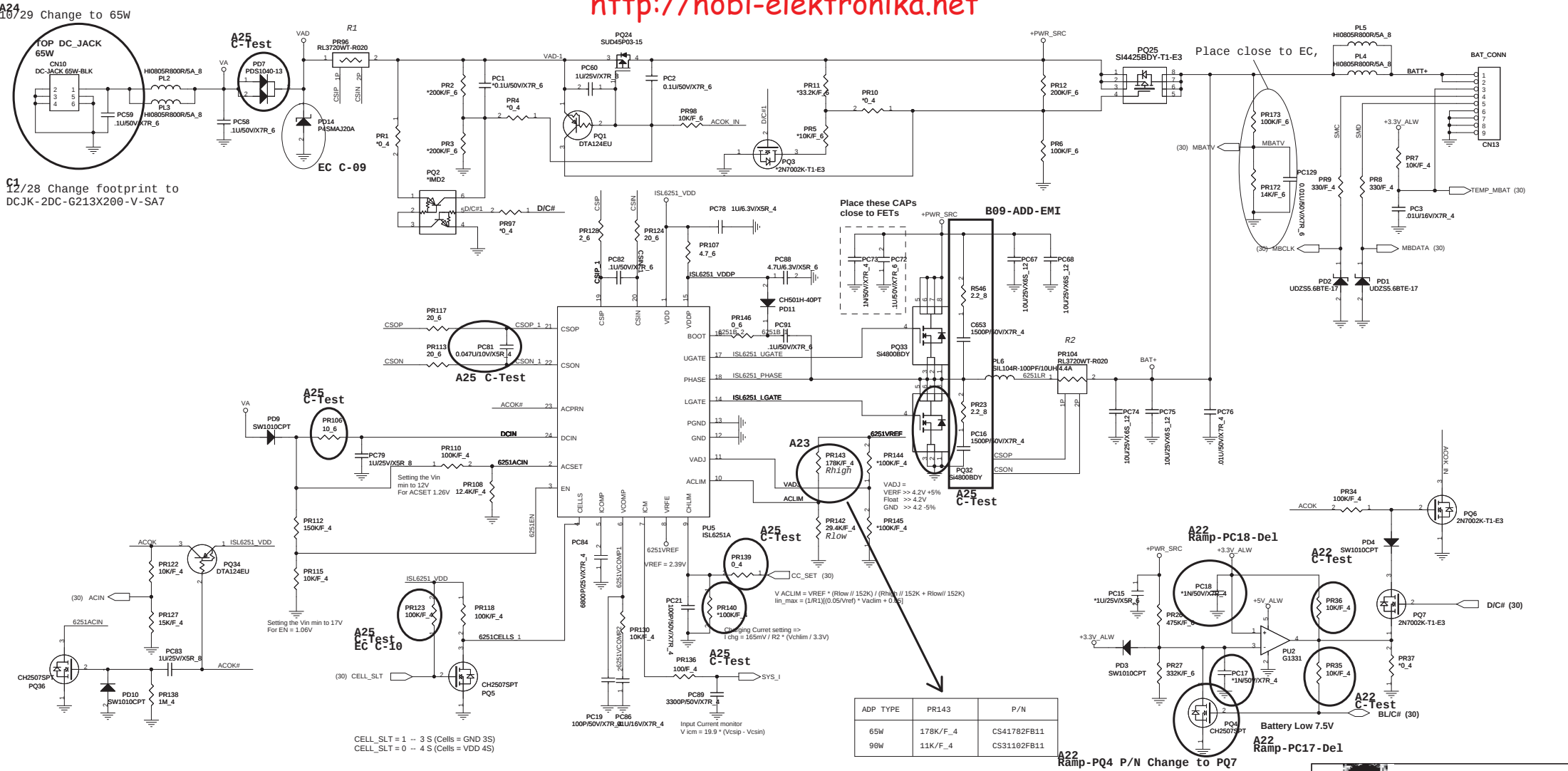


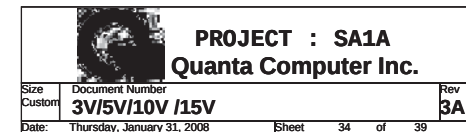
1.35A need 60 mil

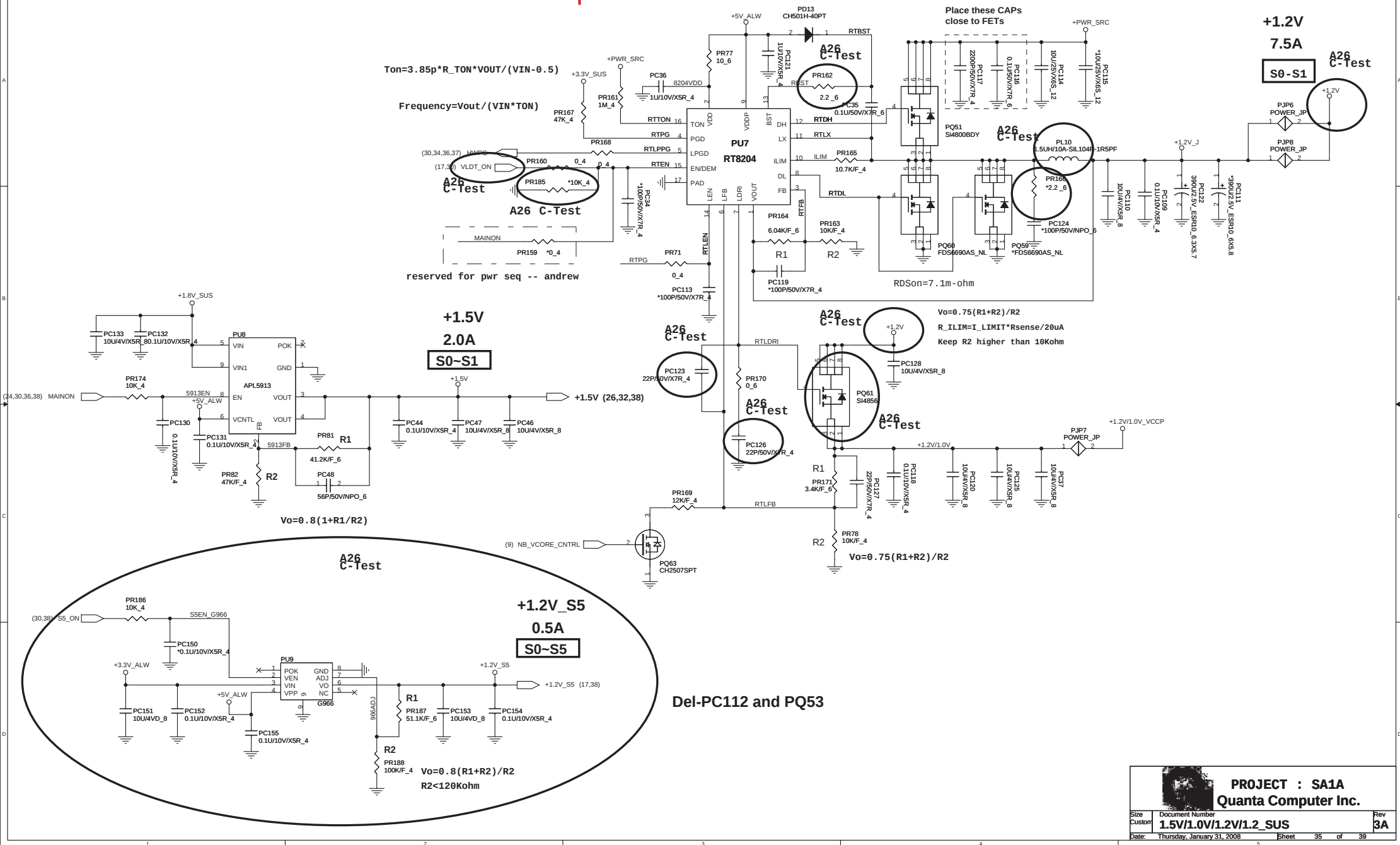
0.75A need 30~40 mil

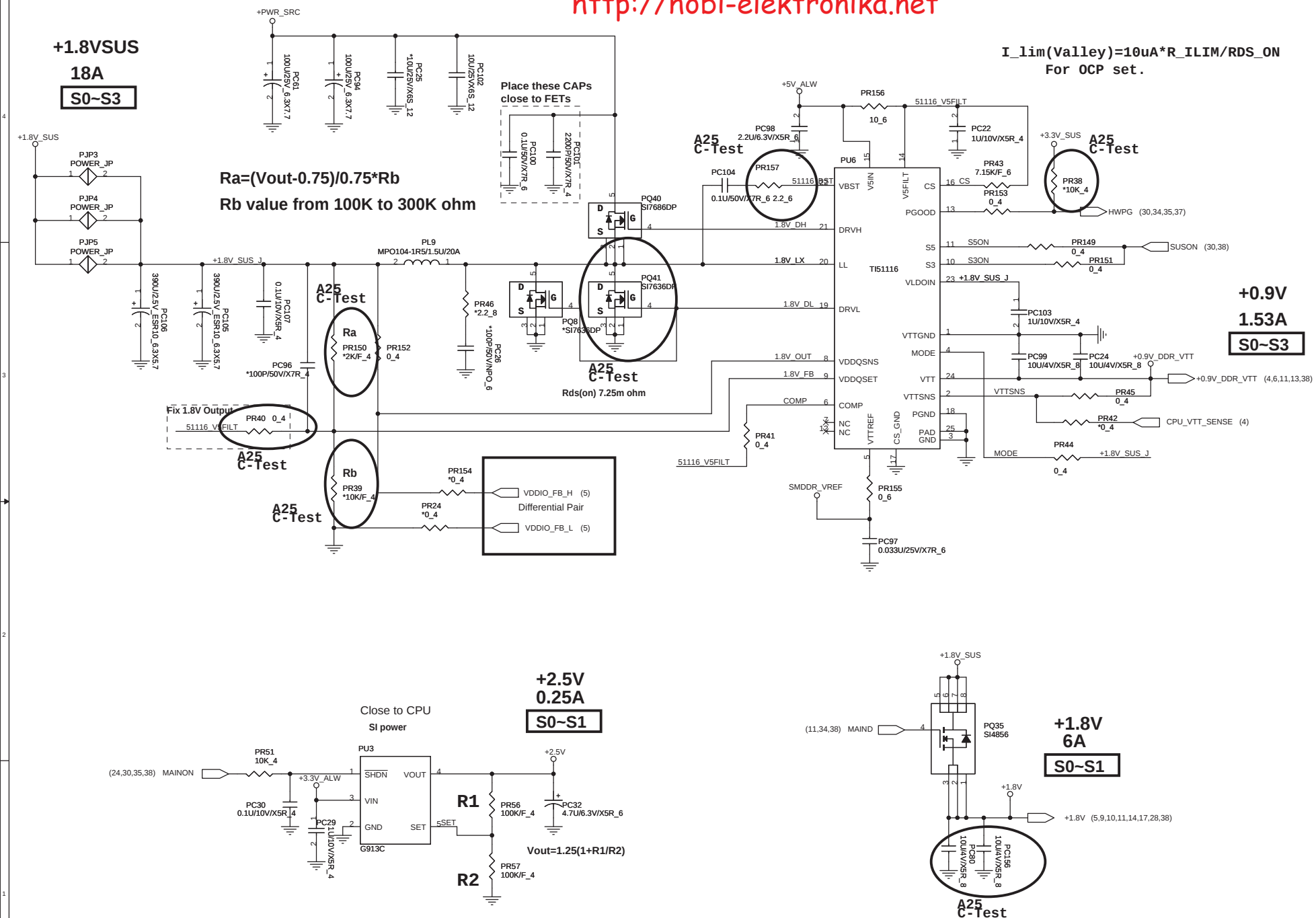


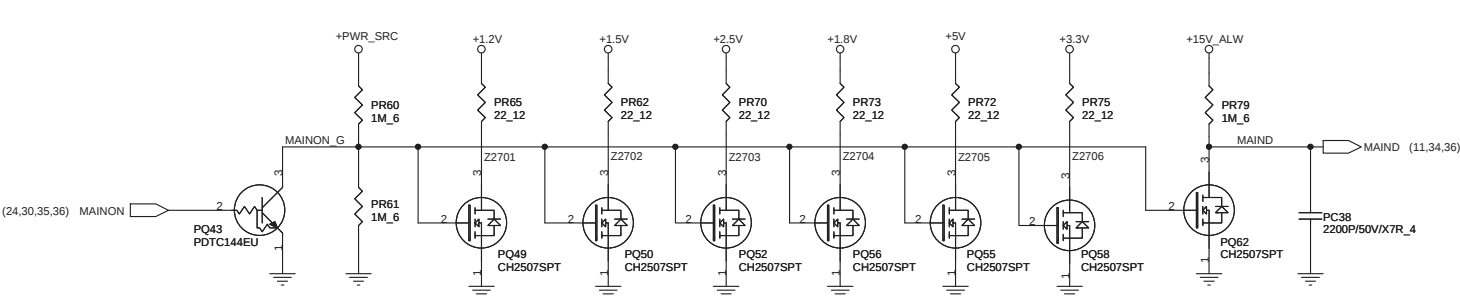
EC B-24



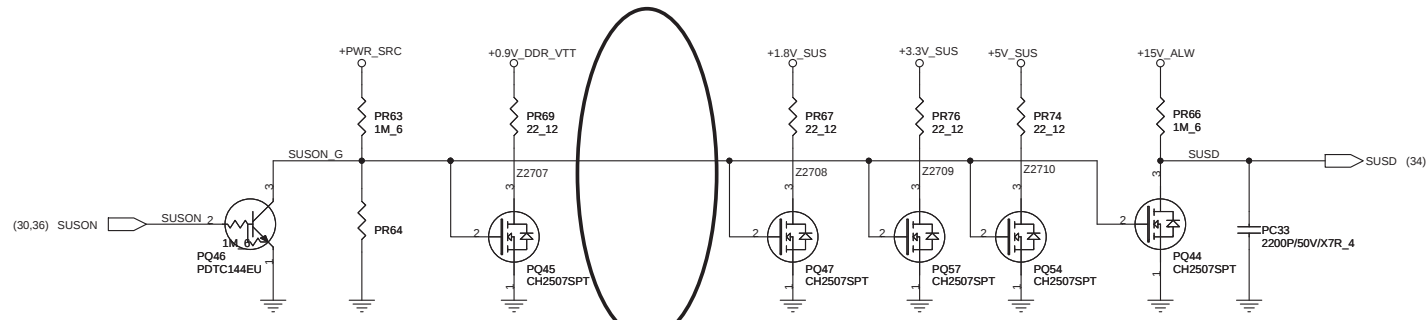
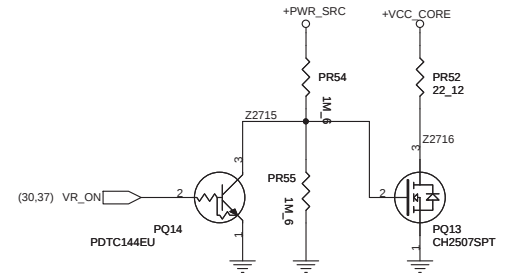




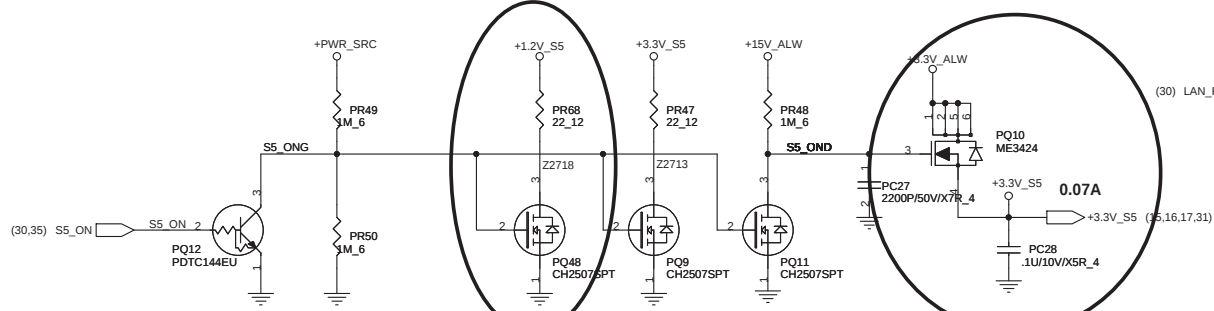




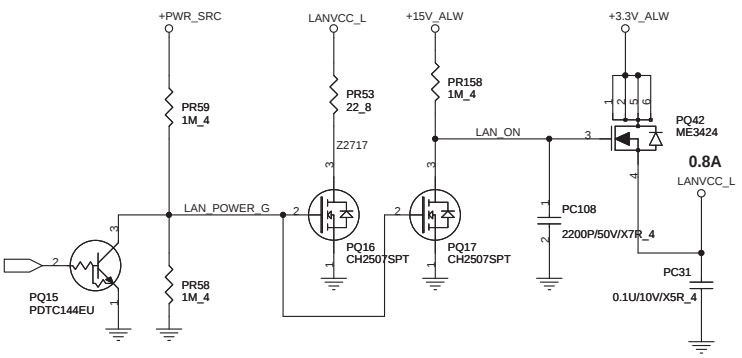
C-test-Del +1.2V_SUS



A27
C-test-Add +1.2V_S5



C-test-reserve 4A



A01. For EMI reserve but no stuff.
A02. Reference AMD demo circuit don't add capacitor.
A03. ADM suggest by pass directly, for single core and dure core start-up issue.
A04. ADM suggest by pass HDMI_DET directly for TMDS directly.
A05. Change CN22 Pin connection.
A06. Change Power rail.
A07. Change KBSMI# to new GPIO for S/W request.
A08. Add New-Card power controll Pin.
A09. Modify STRAP Pin setting.
A10. Solve Start-up "FF" issue.
A11. Change Power rail.
A12. Use +15V let Q10 turn-on fully.
A13. Base on AMD suggest and Demo circuit don't connection those parts.
A14. AMD suggest use 60 Ohm Res , so we use 120//120=60 Ohm.
A15. Modify by Realtek suggestion for power saving.
A16. Change Power soucer by Realtek suggestion.
A17. Del capacitor by Realtek suggestion for signal loading capacitor.
A18. Modify Pin define for common design.
A19. Solve some ODD can't detection issue.
A20. Change ESD component P/N.
A21. Change EC net to correct function.
A22. Del PC17, PC18 and change PR35 ,PR36 to slove battery learnning can't discharge issue.
A23. Change Resistor 65W charge setting.
A24. Modify P/N for common design.
A25. Change by Power for fine tune some part's volume or footprint.
A26. Change power circuit for power budget and slove leakge issue.
A27. Change Power rail.
A28. For EMI reserve.

B-01 / Page 2 / Add Cap for AMD suggestion.
B-02 / Page 9 / USB performance
B-03 / Page 9 / Change Value for AMD suggestion to PASS HDMI test.
B-04 / Page 16 / Requirement from AMD.
B-05 / Page 18 / Change value to solve HDMI issue.
B-06 / Page 19 / Change to FDV301N to solve HDMI issue.
B-07 / Page 26 / Connector to WLAN_RF_OFF#.
B-08 / Page 31 / Delete.
B-09 / Page 33 / Add for EMI suggestion.
B-10 / Page 37 / Add for EMI suggestion.
B-11 / Page 2 / Reserve for EMI suggestion.

EC C-01 / Page 5,10 / ADD EMI solution
EC C-02 / Page 5 / The PWM output do not need a series 100K and a 0.1u cap. So R378 change to 0 ohm , C534 remove Cap.
EC C-03 / Page 9,14,15 / Insert 10K resistor for ESD.
EC C-04 / Page 14 / Change to non-insert.
EC C-05 / Page 20 / Change Resistor from 2.2K to 4.7K.
EC C-06 / Page 20 / Change Resistor from 2.2K to 6.8K.
EC C-07 / Page 20 / Change to non-insert.
EC C-08 / Page 31 / Change to non-insert for ESD.
EC C-09 / Page 33 / Add PD14 for Power plug issue.
EC C-10 / Page 33 / Insert 100K for Battery charger issue.
EC C-11 / Page 37 / PQ29 Change TO PQ28 , PQ30 Change TO PQ31 for EMI.
EC C-12 / Page 19 / Base on AMD requirement we will change R539 to CX8PG330007 , Change R540 to non-insert.(Change FAI stage).
EC C-13 / Page 09 / Insert 100K for HDMI hot plug issue(Change FAI stage).
EC C-14 / Page 31 / Change Capacitor from 0.1U to 220P for EMI(Change FAI stage).
EC C-15 / Page 24 / C461,C460,C459,C458 change to ASM(Change FAI stage).
EC C-16 / Page 14 / R391 change to ASM(Change FAI stage).
EC C-17 / Page 24 / R498 change to ASM(Change FAI stage).